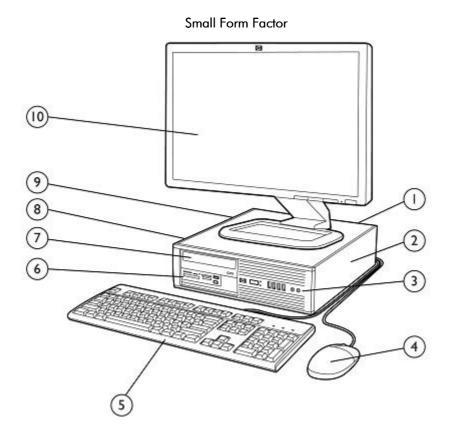
### Overview



1. Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort and VGA video interfaces, and audio in/out jacks

2. Low profile expansion slots include (1) PCI slot, (1) PCI Express x1 slots and (2) PCI Express x16 graphics slot

NOTE: 2nd PCIe x16 slot has x4 connectivity.

3. Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack

- 4. HP Optical Mouse
- 5. HP Keyboard

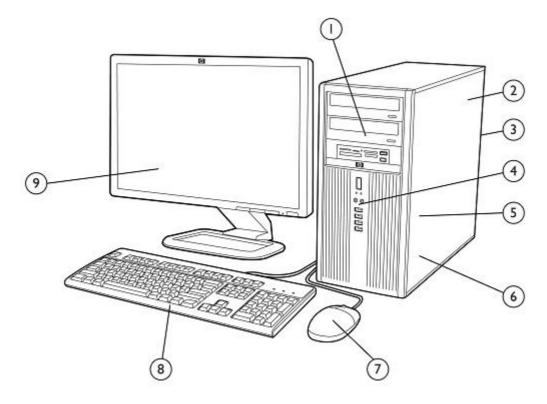
6. 3.5" external drive bay supporting a media card reader or a secondary hard disk drive

- 7. 5.25" external drive bay supporting an optical disk drive
- 8. 3.5" internal drive bay supporting primary hard disk drive
- 9. 240W standard or high efficiency Power Supply
- 10. HP Monitor (sold separately)



#### Overview

**Convertible Minitower** 



1. (3) 5.25" external drive bays supporting optical disk drives, removable hard disk drives, or the HP Media Card Reader

2. 320W standard or high efficiency Power Supply

3. Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort and VGA video interfaces, and audio in/out jacks

4. Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack

5. (3) 3.5" internal drive bays supporting multiple hard disk drives

6. Full height expansion slots include (3) full-length PCI slots, (1) PCI Express x1 slot, and (2) full-length PCI Express x16 graphics slots

NOTE: 2nd PCle x16 slot has x4 connectivity.

- 7. HP Optical Mouse
- 8. HP Keyboard
- 9. HP Monitor (sold separately)



## HP Compaq 8100 Elite PC

# QuickSpecs

### Overview

## At A Glance

- Designed for long-term deployment within medium to large commercial and institutional organizations
- Guaranteed lengthy purchase lifecycles and image stability
- Standard efficiency or 89% high efficiency energy saving power supplies; high efficiency power supplies certified 80 PLUS® Gold by Ecos Consulting
- ENERGY STAR qualified models available; all ENERGY STAR qualified models are certified EPEAT Gold
- Intel® Q57 Express chipset
- Intel® Core<sup>™</sup> and Pentium® processors
- DDR3 Synchronous Dynamic Random Access Memory (SDRAM)
- Software image fully compatible across all models and form factors
- BIOS developed and engineered by HP for better security, manageability and software image stability
- Integrated dual independent monitor support via both a VGA and DisplayPort video/audio interface
- Created using industry leading Design for Environment standards
- Intel® Core<sup>™</sup> Processor with vPro<sup>™</sup> Technology (on select models)
- Supports industry standard management protocols including DASH and Intel® Standard Manageability
- Models can be configured with multiple hard disk drives in a RAID array
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Tool-less serviceability features for easier upgrades and repairs
- Choice of professional chassis form factors to accommodate the desired mix between expandability and size
- HP unique Convertible Minitower chassis delivers true expandability, and is easily configured for vertical or horizontal orientation



### Standard Features and Configurable Components (availability may vary by country)

### **Operating Systems**

Preinstalled	<ul> <li>Genuine Windows Vista Business (32-bit)<sup>1</sup></li> <li>Genuine Windows Vista Home Basic (32-bit)1</li> <li>Genuine Windows 7 Professional Edition (32-bit)<sup>2</sup></li> <li>Genuine Windows 7 Professional Edition (64-bit)<sup>2</sup></li> <li>Genuine Windows XP Professional (available through downgrade rights from Genuine Windows 7 Professional)<sup>2,3</sup></li> <li>Genuine Windows 7 Home Premium Edition (32-bit or 64-bit)<sup>2</sup></li> <li>Genuine Windows 7 Home Basic Edition (32-bit)<sup>2</sup></li> <li>FreeDOS</li> </ul>
Supported	<ul> <li>Genuine Windows Vista Enterprise Edition<sup>1</sup></li> <li>Genuine Windows 7 Enterprise Edition<sup>2</sup></li> </ul>

- Genuine Windows 7 Ultimate Edition<sup>2</sup>
- Novell SUSE Linux Enterprise Desktop 114

Certified

• Red Hat Desktop RHEL<sup>4</sup>

<sup>1</sup> Certain Windows Vista product features require advanced or additional hardware. See www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: www.windowsvista.com/upgradeadvisor

<sup>2</sup> System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details.

<sup>3</sup> Windows 7 Professional disk may be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order at least 25 customer systems with the same custom image.

<sup>4</sup> The following features are not supported on Linux certified systems:

- HP 22-in-1 media card reader
- Trusted Platform Module (TPM) 1.2 Security Chip
- Intel Gigabit CT Desktop NIC Card
- Broadcom NetXtreme GbE Ethernet Plus NIC
- HP 802.11b/g/n wireless NIC
- LSI 56K Int'l SoftModem
- HP USB Smartcard keyboard
- HP Serial port adapter
- HP Parallel port adapter
- HP eSATA port adapter
- HP FireWire/IEEE 1394 I/O card
- RAID
- Media Card Reader (22-in-1) with 1394 port
- NVIDIA NVS G310 SH Graphics Card



## Standard Features and Configurable Components (availability may vary by country)

- NVIDIA Quadro NVS 290 Graphics Card
- NVIDIA Quadro NVS 295 Graphics Card
- ATI Radeon HD 4550 Graphics Card
- ATI Radeon HD 4650 DP Graphics Card

Value Added Software (included with all models; not included when configured with FreeDOS)

- HP ProtectTools Security Suite
- HP Software Management Agent
- Computrace for Desktops agent (optional)\*

- HP Insight Diagnostics
- PDF Complete

\* Computrace available as an optional aftermarket service; separate software and subscription are required

Value Added Software (included with select models; not included when configured with FreeDOS)

- Computer Setup Utility
- McAfee Total Protection Anti-Virus\*
- Roxio Creator Business
- HP Power Assistant

- Microsoft Office Trial Version
- Mozilla Firefox for HP Virtual Browser
- Corel WinDVD

\* 60 day trial period for McAfee Total Protection for Small Business software. Internet access required to receive updates. First update included. Subscription required for updates thereafter

HP Client Management Solutions (available for free download from the Internet)

http://www.hp.com/go/easydeploy)

- HP Client Automation Starter\*
- HP SoftPaq Download Manager

\* Available from your HP Sales Representative or HP Channel Partner

#### Value Added Services and Features

- HP Stable Platform Program
- Intel Stable Platform Program
- Business-to-Business Portals
- HP Global Series Services

- HP Client Catalog for Microsoft SMS
- HP Systems Software Manag
- Factory Express Deployment and Lifecycle Services
- Intel Standard Manageability
- Intel<sup>®</sup> Core<sup>™</sup> processor with vPro<sup>™</sup> technology
- Trusted Platform Module (TPM) v1.2 TPM module disabled where restricted by law; for example, Russia.

### Service and Support

On-site warranty and service<sup>1</sup>: three year (3/3/3) limited warranty and service offering delivers three years of parts, labor and on-site repair. Response time is next business day<sup>2</sup> and includes free telephone support<sup>3</sup> 24 x 7. Global coverage<sup>2</sup> ensures any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. Some countries/regions do not offer one year onsite and labor.

<sup>1</sup> Terms and conditions may vary by country. Certain restrictions and exclusions apply.

<sup>2</sup> On-site services may be provided pursuant to a service contract between HP and an authorized HP third party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.



### Standard Features and Configurable Components (availability may vary by country)

<sup>3</sup> Technical telephone support applies only to HP configured, HP and HP qualified third party hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

Power Supply	Small Form Factor	Convertible Minitower	
Standard Efficiency	240W active PFC	320W active PFC	
High Efficiency*	240W active PFC 87/89/85% efficient at 20/50/100% load	320W active PFC 87/89/85% efficient at 20/50/100% load	
Operating Voltage Range	90 – 264 VAC	90 – 264 VAC	
Ports			
USB 2.0	Front – four (4) ports Rear – six (6) ports		
Serial	One port standard; second port available optic	onally	
Parallel	One port available optionally		
eSATA	One port available optionally		
PS/2	Color coded support for keyboard (purple) and	mouse (green)	
Video	VGA and DisplayPort provide integrated dual i	ndependent monitor support	
DVI output	Available via optional DisplayPort to DVI Adapter		
Audio	Front – microphone & headphone Rear – line input (supports microphone or line input), line out NOTE: See Audio/Visual section for information on re-taskable audio ports. DisplayPort also supports audio.		
NIC	Industry standard RJ-45 port accesses the integra	ated network interface controller	
Slots			
Type and quantity	(1) PCI (1) PCI Express x1 (2) PCI Express x16	(3) PCI (1) PCI Express x1 (half-length) (2) PCI Express x16	
Slot specifications	Low Profile 25W max. cards	Full height 75W max. for cards in both x16 slots Primary x16 slot supports 75W or 35W card Secondary x16 slot supports 35W card when primary slot is limited to 35W card Secondary slot functions electrically as an x4 slot	

### Chipset

Intel Q57 Express supporting Intel® Core™ processor with vPro™ technology

### Processors

NOTE: all models configured with Intel® Core™ processors with 4 cores require a discrete graphics solution

#### Intel Pentium Processors:

Intel Pentium G6950 Processor 2.80 GHz, 3M total cache 2 cores/2 threads Integrated Intel® HD Graphics

Intel Core i3 Processors:



### Standard Features and Configurable Components (availability may vary by country)

#### Intel Core i3-530 Processor

2.93 GHz, 4M total cache 2 cores/4 threads Integrated Intel® HD Graphics

#### Intel Core i3-540 Processor

3.06 GHz, 4M total cache 2 cores/4 threads Integrated Intel® HD Graphics

#### Intel Core i5 Processors:

Intel Core i5-650 Processor 3.2 GHz, 4M total cache 2 cores/4 threads Integrated Intel® HD Graphics Intel® Core™ processor with vPro™ technology Intel® Stable Image Platform Program (SIPP)

#### Intel Core i5-660 Processor

3.33 GHz, 4M total cache 2 cores/4 threads Integrated Intel® HD Graphics Intel® Core™ processor with vPro™ technology Intel® Stable Image Platform Program (SIPP)

#### Intel Core i5-670 Processor

3.46 GHz, 4M total cache 2 cores/4 threads Integrated Intel® HD Graphics Intel® Core™ processor with vPro™ technology Intel® Stable Image Platform Program (SIPP)

#### Intel Core i5-750 Processor

2.66 GHz, 8M total cache 4 cores/4 threads Requires a discrete graphics solution

## Intel Core i5-750S (low power) Processor

2.40 GHz, 8M total cache4 cores/4 threadsRequires a discrete graphics solution

#### Intel Core i7 Processors:

Intel Core i7-860 Processor 2.80 GHz, 8M total cache 4 cores/8 threads Requires a discrete graphics solution Intel® Core™ processor with vPro™ technology Intel® Stable Image Platform Program (SIPP)

#### Intel Core i7-870 Processor

2.93 GHz, 8M total cache 4 cores/8 threads Requires a discrete graphics solution Intel® Core™ processor with vPro™ technology Intel® Stable Image Platform Program (SIPP)



### Standard Features and Configurable Components (availability may vary by country)

### Redundant Array of Independent Drives (RAID)

- DriveLock is supported while in RAID mode. Users can manage the DriveLock password from within F10 Setup. Locked drives will be displayed as such in the RAID option ROM interface.
- Hard drive information can be viewed within F10 Setup while in RAID mode. Previously, the hard drives will not appear in Drive Configuration when switching to RAID mode.
- DPS Self Test can be executed on physical hard drives while in RAID mode.
- The RAID Setup Utility (accessed through CTRL-I) can be protected by the F10 Setup password.

NOTE: RAID 1 is the only RAID configuration offered via factory configurations. The pre-configured systems:

- Are complete RAID systems and have both drives installed. If the CMT is configured with three hard disk drives, the third drive is would be unpartitioned and not part of the RAID array
- Have the necessary Option ROM configuration.
- Are pre-loaded and pre-installed with all required Intel software.
- Include a preinstalled operating system that is mirrored mode out of the box.

Please refer to the HP White Paper titled "Advanced Host Controller Interface (AHCI) and Redundant Array of Independent Disks (RAID) on HP Compaq 8100 Elite Series PCs" at: http://www.hp.com for more information and instructions.

## DDR3 Synchronous DRAM NON-ECC System Memory

Memory upgrades are accomplished by adding single or multiple DIMMs of the same or varied sizes. This chart does not represent all possible memory configurations. The HP Compaq 8100 Elite Series PC supports non-ECC DDR3 PC3-10600 (1333 MHz)\* and PC3-8500 (1066 MHz)\* memory.

**CAUTION:** You must shut down the computer and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

Supports up to 16 GB of DDR3 SDRAM using DIMM modules. Slot 1 is black and must always be populated. Not all memory configurations possible are represented below.

**NOTE:** For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.



### Standard Features and Configurable Components (availability may vary by country)

Total Memory	Slot			
	Char	nnel A	Char	nnel B
	1 (black)	2 (white)	3 (white)	4 (white)
1GB (single channel)	1 GB			
2 GB (dual channel)	1 GB		1 GB	
4 GB (dual channel)	1 GB	1 GB	1 GB	1 GB
8 GB (dual channel)	2 GB	2 GB	2 GB	2 GB
16 GB (dual channel)	4 GB	4 GB	4 GB	4 GB

\* The Intel Q57 Express chipset includes a built-in Management Engine (ME), which allocates memory for manageability functions. Management Engine memory is shared with system memory. If the PC contains a single DIMM, 16 MB of memory is pre-allocated for it at system startup. If the PC contains two DIMMs, 32 MB of memory is pre-allocated. This memory is not made available to the operating system, just as pre-allocated video memory is not available.

### **Memory Configurations**

1GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (1 x 1GB) 2GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (1 x 2GB) 2GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (1 x 2GB) 3GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (1GB + 2GB) 4GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (1 x 4GB) 4GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (2 x 2GB) 8GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (2 x 4GB) 8GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (4 x 2GB) 16GB DDR3 SDRAM PC3-10600 (1333MHz) non ECC (4 x 4GB)

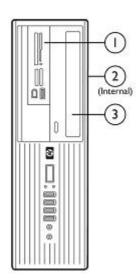
Expandability	Small Form Factor	Convertible Minitower
PCI slot	(1) slot Low profile (2.5"); Half length (6.6") 25W max. power	(3) slots Full height (4.2"); Full length 25W max. power
PCI Express x16 slot	(2) slots Low profile (2.5"); Half length (6.6") 25W max. power Secondary slot functions electrically as an x4 slot	Full height (4.2"); Full length 75W max. for cards in both x16 slots Primary x16 slot supports 75W or 35W card Secondary x16 slot supports 35W card when primary slot is limited to 35W card Secondary slot functions electrically as an x4 slot
PCI Express x1 slot	<ul><li>(1) slot</li><li>Low profile (2.5"); Half length (6.6")</li><li>10W max. power</li></ul>	(1) slot Half height; Half length 10W max. power
External Drive Bays		



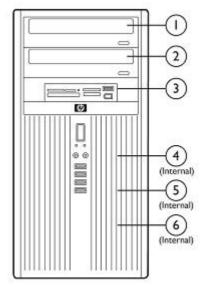
### Standard Features and Configurable Components (availability may vary by country)

3.5"	(1) bay available for Media Card Reader	N/A	
	unless used for a secondary hard drive	NOTE: A 3.5" device can be used in	
		5.25" bay with an adapter.	
5.25"	1 bay (8.19" depth)	3 bays	
		Top two bays accept drives up to 8.19" depth	
		Bottom bay accepts drives up to 5.7"depth	
Internal Drive Bays	1 bay for primary hard disk drive	3 bays for 3.5″ hard disk drives	
	A secondary HDD can be installed in 3.5"	2.5" SSD can be installed with an	
	external bay if not used for an external device	adapter bracket	
Hard Drive Controller	Serial ATA with support for SATA	1.5-Gb/s and 3.0-Gb/s hard drives	
SATA Interfaces	(4) Serial ATA interfaces	(5) Serial ATA interfaces	
	NOTE: Three common SATA ports and	NOTE: Four common SATA ports and	
	one that can optionally be used for eSATA	one that can optionally be used for eSATA	
Host SATA Controller	Advanced Host Controller Interface (AHCI) Revision 1.2. The specification includes a description		
L	of the hardware/software interface between system software and the host controller hardware.		

#### Small Form Factor



#### Convertible Minitower



Storage – Drive Support						
		SFF			CMT	
	MCR	ODD	HDD SSD	MCR	ODD	HDD SSD
Quantity Supported	1	1	2	1	2	3
Position	1	3	2,1	3	1,2	4,5,6



Standard Features and Configurable Components (availability may vary by country)

#### Hard Disk Drives

160GB Hard Disk Drive7,200 rpm, 8MB cache, 3.0 GB/s, 3.5" drive160GB Hard Disk Drive10,000 rpm, 16MB cache, 3.0 GB/s, 2.5" drive (includes 3.5" adapter)160GB Removable Hard Disk Drive7,200 rpm, 8MB cache, 3.0 GB/s

250GB Hard Disk Drive 7,200 rpm, 8MB cache, 3.0 GB/s, 3.5" drive 250GB Removable Hard Disk Drive 7,200 rpm, 8MB cache, 3.0 GB/s

320GB Hard Disk Drive 7,200 rpm, 8MB cache, 3.0 GB/s, 3.5″ drive

500GB Hard Disk Drive 7,200 rpm, 16MB cache, 3.0 GB/s, 3.5" drive

<u>1 TB Hard Disk Drive</u> 7,200 rpm, 16MB cache, 3.0 GB/s, 3.5″ drive

#### Solid State Drives

64GB Solid State Drive 2.5" drive (includes 3.5" adapter)

#### Optical Disc Drives (5.25")

DVD-ROM Drive<sup>1</sup> SuperMulti LightScribe DVD Writer Drive<sup>1,2,3</sup> Blu-Ray Writer Drive <sup>1</sup>For playing DVDs, Corel WinDVD 8 <sup>2</sup>For writing CDs, choice of Sonic/Roxio Easy Media Creator 9 orRoxio Business Creator 10 <sup>3</sup>For writing CDs and DVDs, video editing and authoring DVDs, choice of Sonic/Roxio Easy Media Creator 9 or Roxio Business Creator 10

#### Media Card Readers

Media Card Reader (22-in-1) Media Card Reader (22-in-1) with 1394 port



Standard Features and Configurable Components (availability may vary by country)

### Security

Trusted Platform Module (TPM) 1.2<sup>1</sup> Stringent Security (via BIOS)<sup>2</sup> SATA Port Disablement (via BIOS) Drive Lock **RAID** Configurations HP ProtectTools security software Serial, Parallel, USB enable/disable (via BIOS) Optional USB Port Disable at factory (user configurable via BIOS) Removable Media Write/Boot Control Power-On Password (via BIOS) Setup Password (via BIOS) Solenoid Hood Lock / Sensor Support for chassis padlocks and cable lock devices <sup>1</sup>TPM module disabled where use is restricted by law; for example, Russia. <sup>2</sup>This setting is defaulted to disable, but when enabled, the PW jumper will not clear the BIOS pre-boot authentication passwords.

#### Network Interface Connection

Intel 82578 GbE Network Connection (integrated) Intel Gigabit CT Desktop NIC Card Broadcom NetXtreme GbE Ethernet Plus NIC (PCle x1) NOTE: The integrated network connection is required to support the vPro Technology features.

HP 802.11 b/g/n Wireless NIC (PCle x1) NOTE: These wireless network interface solutions will disable the vPro Technology features.

#### Modem

LSI Hi-Speed 56K International Soft Modem (PCle x1)

#### Graphics

Integrated graphics with Intel Pentium processor, Intel Core i3 processors, and select Intel Core i5 processors:

Intel HD Graphics (integrated) on selected models

Available discrete graphics cards: NVIDIA GeForce 310 DP PCle x16 Graphics Card Nvidia Quadro NVS 290 Graphics Card Nvidia Quadro NVS 295 Graphics Card ATI Radeon HD 4550 Graphics Card



Standard Features and Configurable Components (availability may vary by country)

ATI Radeon HD 4650 DP (1GB) PCIe x16 Graphics Card (CMT only) HP ADD2 SDVO + DVI-D Video Adapter

HP DisplayPort to DVI-D Adapter

HP DisplayPort to VGA Adapter

#### Audio/Visual

High Definition Audio with Realtek ALC261 codec (all ports are stereo)

Microphone/Headphone\* and dedicated headphone front ports

Line-out and Line-In rear Ports\*

Multi-streaming capable\*

Internal Speaker (standard)

HP Thin USB Powered Speakers

HP TV Tuner (Americas) PCIe x1 Card

\* The front microphone port is re-taskable as a Line-in, Microphone-in or Headphone . Rear audio input ports are re-taskable as Line-in or Microphone-in. External speakers must be powered externally. Multistreaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks. This allows for different audio applications to use separate audio ports on the system. For example, the front jacks could be used with a headset for a communications application while the rear jacks are being used with external speakers and a multimedia application.

#### Input Devices

HP PS/2 Standard Keyboard HP USB Standard Keyboard HP USB SmartCard Keyboard HP USB Mini Keyboard HP USB & PS/2 Washable Keyboard

PS/2 Optical Scroll Mouse USB Optical Scroll Mouse USB Laser Scroll Mouse

### Miscellaneous

HP FireWire (IEEE 1394) Card HP Serial Port Adapter HP Parallel Port Adapter HP eSATA Port Adapter HP Small Form Factor PC Tower Stand Configure CMT in desktop orientation



After-Market Options (availability may vary by region)

Communications	Part Number
HP Wireless 802.11 b/g/n NIC Card	FH971AA
Broadcom NetXtreme GbE Ethernet Plus NIC Card	FS215AA
Intel Gigabit CT Desktop NIC Card	FH969AA
LSI Hi-Speed 56K Int'l Soft Modem Card	FH970AA
RJ11 Modem Adapter Kit	DC131C
NOTE: The use of a NIC Card (wired or wireless) will disable the vPro Technology features.	
Graphics	Part Number
ATI Radeon HD 4550 Graphics Card	AT042AA
ATI Radeon HD 4650 DP (1GB) PCle x16 Graphics Card	VN566AA
Nvidia Quadro NVS 290 Graphics Card	KG748AA
Nvidia Quadro NVS 295 Graphics Card	FY943AA
Nvidia GeForce 310 DP PCle x16 Graphics Card	VG885AA
DMS59 DVI Dual-head Connector Cable	DL139A
HP DVI to DVI cable	DC198A
HP DisplayPort To DVI-D adapter	FH973AA
HP DisplayPort To DL DVI-D adapter	NR078AA
HP DisplayPort to VGA Adapter	AS615AA
HP DisplayPort Cable Kit	VN567AA
Hard Disk Drives	Part Number
HP 160GB SATA NCQ SMART IV Hard Disk Drive	PY277AT
HP 250GB SATA NCQ SMART IV Hard Disk Drive	PY278AA
HP 500GB SATA NCQ SMART IV Hard Disk Drive	KW347AA
HP eSATA Adapter	FH966AA
HP Removable SATA Hard Drive Enclosure (frame & carrier)	RY102AA
HP Removable SATA Hard Drive Enclosure (Carrier Only)	RY103AA



After-Market Options (availability may vary by region)

Input/Output Devices	Part Number
HP PS/2 Standard Keyboard	DT527A
HP USB Standard Keyboard	DT528A
HP USB Gray Keyboard	DT529A
HP 2.4GHz Wireless Keyboard & Mouse	NB896AA#xxx
HP USB Mini Keyboard	AS601AA
HP USB Washable Keyboard	VF097AA
HP PS/2 Optical Scroll Mouse	EY703AA
HP USB Optical Scroll Mouse	DC172B
HP USB Laser Mouse	GW405AA
DDR3 SDRAM System Memory	Part Number
1 GB DIMM	AT023AA
2 GB DIMM	AT024AA
HP 4-GB PC3-10600 (DDR3-1333 MHz) DIMM	VH638AA
HP Monitors	Part Number
HP L1506 15 TFT Flat Panel Monitor – Analog only	PX848AA
HP L1706 17 TFT Flat Panel Monitor – Analog only	ΡΧ849ΑΑ
HP L1740 17 LCD Flat Panel Display – Analog/Digital	PL766AA
HP L1745 17 TFT Flat Panel Display – Analog/Digital	GE178AA
HP L1906 19 TFT Flat Panel Display – Analog only	PX850AA
HP L1940T 19 TFT Flat Panel Display – Analog/Digital	EM869AA
HP LP1965 19 TFT Flat Panel Display – Analog/Digital	RA373AA
HP L2045w TFT Flat Panel Display – Analog/Digital	RD125AA
HP L2065 20 TFT Flat Panel Display – Analog/Digital	EF227A4
HP LP2465 24 TFT Widescreen Flat Panel Display – Analog/Digital	EF224A4
HP LP3045 30 TFT Flat Panel Display – Digital	EZ320A8
HP w19 Wide LCD Display – Analog/Digital	EM885AA

HP s7540 17 (16.0 vis) CRT Monitor

PF997AA

This is only representative, not an exhaustive list. All HP Monitors are supported except the 30-inch model. The 30-inch model can be added, but it requires a special graphics card.



After-Market O	ptions (c	availability	' may vary	by region)
		/	/ /	/ 0 /

Multimedia Devices	Part Number	
HP Thin USB Powered Speakers	KK912AA	
DVD-ROM Drive	AR629AA	
SuperMulti LightScribe Drive	AR630AA	
Blu-Ray Writer Drive	AR482AA	
Removable Media Storage	Part Number	
HP USB External Diskette Drive	DC141B	
HP Media Card Reader (22-in-1)	AR941AA	
HP Media Card Reader (22-in-1) with FireWire (IEEE 1394)	AR942AA	
Security Devices	Part Number	
HP/Kensington MicroSaver Cable Lock	РС766А	
HP Business PC Security Lock	PV606AA	
HP (2009) SFF Wall Mount/Security Sleeve	VN570AA	
HP (CMT) Solenoid Lock and Hood	DE618A	
HP ProtectTools Version 5.0 (1 User) Software	VR893AA	
HP USB SmartCard Keyboard	ED707AA	
Software Solutions	Part Number	
HP Client Automation Standard	T3488AA (qty 1) TA599AA (qty 10) TA600AA (qty 100) TA601AA (qty 500) T3489AA (qty 1000)	
Stands and Accessories	Part Number	
HP (2009) SFF Tower Stand	VN568AA	
HP Serial Port Adapter	PA716A	
HP Parallel Port Adapter	KD061AA	
HP 5.25″ Blank Bezel Kit (50 pack)	DC177B	
HP FireWire (IEEE 1394) Card	PA997A	



### Technical Specifications

	Small Form Factor	Convertible Minitower
Dimensions		
Chassis	3.95 x 13.30 x 14.9 in	17.63 x 7.00 x 17.5 in
(H x W x D)	100 x 338 x 378.5 mm	447.8 x 177.8 x 444.5 mm
System Volume	790.26 cu in	2160 cu in
	12.95 L	35.4 L
Tower Stand	1.12 x 7.01 x 7.87 in	N/A
(H x W x D)	28.5 x 178 x 200 mm	
Packaging	9.00 x 19.68 x 23.38 in	22.64 x 12.72 x 24.41 in
(H x W x D)	228.6 x 499.9 x 593.85 mm	575.0 x 323 x 620 mm
System Weight*	16.72 lbs	24.54 lbs
	7.6 kg	11.15 kg
Shipping Weight*	17.86 lbs	34.0 lbs
	8.1 kg	15.42 kg
Max Supported Weight	77 lb	77 lbs
(desktop orientation)	35 kg	35 kg
*Configured with 1 hard	drive, 1 optical drive, no diskette drive, and no PCI of	card.

#### Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)*	
	Non-operating: –22° to 140° F(–30° to 60° C)	
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient)	
	Non-operating: 5% to 95% (non-condensing at ambient)	
Maximum Altitude	Operating: 10,000 ft (3048 m)	
(unpressurized)	Non-operating: 30,000 ft (9144 m)	
*Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained		
sunlight Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed		



### Technical Specifications

Power Supply	SFF	CMT
Standard Efficiency	240W standard efficiency	320W standard efficiency
	active PFC	active PFC
High Efficiency*	240W 89% efficient	320W 89% efficient
	active PFC	active PFC
Operating Voltage Range	90 – 264 VAC	90 – 264 VAC
Rated Voltage Range	100 – 240 VAC	100 – 240 VAC
Rated Line Frequency	50/60 Hz	50/60 Hz
Operating Line Frequency	47 – 63 Hz	47 – 63 Hz
Range		
Rated Input Current	4A	5.5A
Rated Input Current with	4A	5.5A
Energy Efficient* Power Supply	/	
Current Leakage	< 275 μA	< 450 μA
(NFPA 99)		
System Heat Dissipation	Typical 198 btu/hr	Typical 222 btu/hr
	(50 kg-cal/hr)	(56 kg-cal/hr)
	Maximum 1063 btu/hr	Maximum 1410 btu/hr
	(268 kg-cal/hr	(356 kg-cal/hr)
System Heat Dissipation	Typical 150 btu/hr	Typical 171 btu/hr
with Energy Efficient* Power	(38 kg-cal/hr)	(43 kg-cal/hr)
Supply	Maximum 941 btu/hr	Maximum 1255 btu/hr
	(237 kg-cal/hr)	(316 kg-cal/hr)
Power Supply Fan	92mm variable speed	92mm variable speed
External Power Adapter		
Dimensions	N/A	N/A
Total Cord Length	N/A	N/A

\*High efficiency power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules

#### **ROM BIOS Information**

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Elite PC into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Select models feature either Intel Standard Manageability or Core 2 processor with vPro Technology.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Computrace agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Business Desktop computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within DOS (Flashbin), BIOS updates from within Windows (HPQFlash), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.



### Technical Specifications

Additional HP BIOS Features

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
  management, allowing operating systems and applications to manage power based on activity and usage. HP Elite models
  use ACPI to provide power conservation features.
- S5 Max Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 1W is S5 (when turned off). When S5 Max Power Savings feature is enabled power to slots is turned off along with WOL functionality.

#### Other Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or poweredoff state without affecting other elements of the system.
- System Management BIOS v2.6
- Intel Wired for Management support; industry wide initiative to make Intel architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

#### Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - O Number of 1-second red LED blinks followed by a 2-second pause, then repeats:
    - 2 processor thermal protection activated
    - 3 processor not installed
    - 4 power supply failure
    - 5 memory error
    - 6 video error
    - 7 PCA failure (ROM detected failure prior to video)
    - 8 invalid ROM, bootblock recovery mode
    - 9 system not fetching code
    - 10 system hang while loading an option ROM
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch



### **Technical Specifications**

- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification

Additional Features	Description
Computrace	Computrace agent included; separate software and subscription required
DT or MT Orientation	Product can be oriented in either a tower or desktop orientation
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Drive Protection System	<ul> <li>DPS Access through F10 Setup during Boot</li> <li>A diagnostic hard drive self test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user.</li> <li>Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced.</li> <li>The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures.</li> </ul>
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I – Drive Failure Prediction SMART II – Off-Line Data Collection	<ul> <li>Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count</li> <li>By avoiding actual hard drive failures, SMART hard drives act as "insurance"</li> </ul>
SMART III – Off-Line Read Scanning with Defect Reallocation	<ul> <li>against unplanned user downtime and potential data loss from hard drive failure</li> <li>IOEDC: I/O Error Detection Circuitry</li> <li>Detects errors in Read/Write buffers on HDD cache RAM</li> </ul>
SMART IV – End-to-End CRC for hard drives	Interface in F10 setup provides confirmation of SMART IV support.



## Technical Specifications - Audio

High Definition Audio	Туре	Integrated
J	High Definition Stereo Codec	Yes - Realtek 4-channel ALC261 codec
	Audio Jacks	Front microphone-In (150-K ohm Input Impedance)
		Rear Line-In/Microphone input (150-K ohm Input Impedance, function is configurable by audio driver)
		Rear Line-Out* (190 ohms Output Impedance, expects at least a 10-K ohm load)
		Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32 ohm load)
		Front Microphone/Headphone jack is re-task able to provide Microphone input, line-in or Headphone output to support connecting two headphones to the front of the system. When configured as a second front headphone output, both front headphone outputs are always driven with the same signal.
		is for the internal speaker only. External speakers need to be powered dio port is re-task able as Line-In or Microphone-In.
	Multistreaming Capable	Multistreaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks.
	Sampling	8 kHz - 192 kHz
	<b>Wavetable Syntheses</b> (software)	Yes - Uses OS soft wavetable
	Analog Audio	Yes
	Number of Channels on Line-Out (mono/stereo)	Stereo (Left & Right channels)
	Internal Audio Speaker Power Rating	1.5 W
	Internal Speaker	Yes
	<b>External Speaker Jack</b> (Line-Out)	Yes



## Technical Specifications - Communications

Intel 82578 Gigabit Network Connection (integrated)	Connector Controller Memory Data rates supported Compliance	RJ-45 Intel 82578 Gigabit platform LAN Connect Networking Controller 24 KB FIFO packet buffer memory 10/100/1000 Mbps • IEEE 802.3i (10Base-T) • IEEE 802.3u (100Base-T) • IEEE 802.3ab (1000Base-T) • IEEE 802.3ab (1000Base-T) • IEEE 802.3ab (Auto-negotiation) • IEEE 802.3af (Power over Ethernet) • IEEE 1588 (Time Sync) • IEEE 802.1ae (MacSec)
	Bus architecture	PCIe-based MAC to PHY interface
	Data transfer mode	PCIe-like interface for 1000 speed, SMBus interface for lower 10/100 speeds.
	Hardware certifications	FCC B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark for European Union
	Power requirement	Requires 3.3V & 1.2V. Power consumption 761 Milliwatts
	Boot ROM support	Yes
	Network transfer mode	Full-duplex
		Half-duplex (not supported for the 1000BASE-T transceiver)
	Network transfer rate	10BASE-T (half-duplex) 10 Mbps
		10BASE-T (full-duplex) 20 Mbps
		100BASE-TX (half-duplex) 100 Mbps
		100BASE-TX (full-duplex) 200 Mbps
		1000BASE-T (full-duplex) 2000 Mbps
	Environmental	<b>Operating temperature</b> 0° to 85° C
	Management capabilities	WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable diagnostic.
	Alerting	AMT 6.0 support
	-	



### Technical Specifications - Communications

Broadcom NetXtreme	Connector	RJ-45		
GbE Ethernet Plus NIC	Controller	Broadcom 5761 PCI-Expr	ess LAN Controller	
	Memory	8 MB NVRAM serial Flash		
	Data rates supported	10/100/1000 Mbps		
	Compliance	IEEE 802.1P, 802.1Q, 80	2.2, 802.3, 802.3AB, 802.3u, and 802.3x	
	Bus architecture	PCI-Express		
	Data path width	Single Channel PCI-Express		
	Data transfer mode	Bus Master DMA		
	Hardware certifications	-	l US NRTL Mark, C-Tick for Australia, BSMI for MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682)	
	Power requirement	1.8W @ 3.3V		
	Boot ROM support	Yes		
	Network transfer mode	Full-duplex		
		Half-duplex (not available	for the 1000BASE-T transceiver)	
	Network transfer rate	10BASE-T (half-duplex) 10	) Mbps	
		10BASE-T (full-duplex) 20	Mbps	
		100BASE-TX (half-duplex) 100 Mbps		
		100BASE-TX (full-duplex) 200 Mbps		
		1000BASE-T (full-duplex)	2000 Mbps	
	Environmental	Operating temperature	32° to 131°F (0° to 55° C)	
		Operating humidity	131° F (55° C) with 5% to 95% non-condensing humidity	
	Dimensions	2.75 in x 4.13 in (7 cm x 10.5 cm), low profile compatible		
	Operating system driver support	Windows Vista 32-bit SP1, professional	, Windows Vista x64 SP1, Windows XP 32 bit	
	Management capabilities	ACPI, WOL and DMI 2.0, ASF2.0, DASH 1.0 and D	PXE 2.0, WfM 2.0, Broadcom mgmt utility, ASH 1.1 profiles	



### Technical Specifications - Communications

Intel Gigabit CT Desktop	Connector	RJ-45	
NIC	Controller	Intel 82574L Gigabit Ethe	ernet Controller
	Memory	40KB configurable transm	nit/receive FIFO Buffers
	Data rates supported	10/100/1000 Mbps	
	Compliance	IEEE 802.1P, 802,1Q, 80 802.3x flow control, 802.	02.2, 802.3, 802.3AB and 802.3u compliant, .1as Time synch offload
	Bus architecture	PCle Base 1.1 (2.5 GT/s)	xl
	Data path width	X1, 250 MB/s, Bi-directio	nal interface
	Data transfer mode	Bus-master DMA	
	Hardware certifications	(see EPS for more certificated EMI: FCC Class B Intel 25-GS3000 Environm EN-55024: 1998 specification EN-55022: Class A 1998 EN-60950-1 first Edition C-Tick specification, Class VCCI Class 1 specification CE specification and CE M UL 60950-1 first Edition s CSA 60950-1 first Edition s CSA 60950-1 first Edition BSMI CNS13438 Class A Korean MIC Class A specification European RoHS directive China RoHS directive	mental Specification. cation (see EPS for details) 3 specification. specification. s A n. Mark. specification. a specification.
	Power requirement	3.3V and 3.3V Aux, 2.1 V	Watts max in 1000Base-T (D0)
	Boot ROM support	Yes	
	Network transfer rate	10BASE-T (half-duplex) 10 Mbps	
		10BASE-T (full-duplex) 20	) Mbps
		100BASE-TX (half-duplex)	100 Mbps
		100BASE-TX (full-duplex)	200 Mbps
		1000BASE-T (full-duplex)	2000 Mbps (actual rate limited by PCI Bus)
	Environmental	Operating temperature	0 °C to 55 °C (operating) −40 to 70 °C (non-operating)
		Operating humidity	85% at 131° F (55° C)
	Dimensions	Low-profile, half-length fo x 119 mm)	orm factor conforming to PCle* CEM v1.1 (55 mm
	Management capabilities		
HP Wireless 802 11b/g/p		3 3 x 4 7 inches (8 5 x 12	2 cm)

HP Wireless 802.11b/g/n Dimensions (L × H) (PCle) Weight Controller System interface

Network standard

Frequency band

3.3 x 4.7 inches (8.5 x 12 cm) 0.08 pounds (40 g) Ralink RT2790 PCIExpress x1 802.11 b/g/n 2.400 - 2.497 GHz



## Technical Specifications - Communications

Operating temperature	14° to 149°F, operating (-	10° to 65°C, operating)	
Storage temperature	-40° to 176°F, non-operating (-40° to 80°C, non-operating)		
Humidity	10-90% operating 5-95% non-operating		
Operating voltage	3.3V +/- 9% 12V +/- 8%		
Power consumption	Platform/WLAN Mode	Power Consumption	
	Maximum Power Consumption	10 Watts	
	Transmit Only	4 Watts maximum averaged power over 1 second	
	Transmit Packet or Active Scanning	1000 mA peak current for 100 microseconds or longer	
	Receive Only Mode or Idle without IEEE PSP mode enabled	3 Watts maximum avera	aged over 1 second
	Idle, with IEEE PSP mode enabled	1.0 Watts maximum averaged over 1 second	
	Transmit Disabled (turned off in software)	50 mW maximum, averaged over 1 second	
	Platform in S3 or S4 (power removed from Low Profile PCI Express Card)	5 mW maximum, avera	ged over 1 second
	000 111		
Output power	802.11b modes	802.11g modes	EWC modes
Output power (approximately)	802.116 modes +19 dBm +/- 1.0 dB maximum	802.11g modes +17 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum (total power
(approximately)	+19 dBm +/- 1.0 dB	+17 dBm +/- 1.0 dB	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains)
	+19 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum Data rate	+17 dBm +/- 1.0 dB maximum (total power
(approximately)	+19 dBm +/- 1.0 dB maximum <b>Mode</b>	+17 dBm +/- 1.0 dB maximum	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps	+17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm -72 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps 6.5 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm -72 dBm -87 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps 6.5 Mbps 54 Mbps 54 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm -72 dBm -87 dBm -82 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps 6.5 Mbps 54 Mbps 81 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm -72 dBm -87 dBm -82 dBm -78 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 18 Mbps 54 Mbps 54 Mbps 54 Mbps 54 Mbps 81 Mbps 162 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -91 dBm -85 dBm -75 dBm -72 dBm -87 dBm -82 dBm -78 dBm -74 dBm
(approximately)	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum <b>Data rate</b> 1 Mbps 11 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps 6.5 Mbps 54 Mbps 81 Mbps 162 Mbps 270 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -85 dBm -72 dBm -72 dBm -87 dBm -82 dBm -78 dBm -78 dBm -74 dBm -74 dBm
(approximately) Receive sensitivity	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 18 Mbps 18 Mbps 54 Mbps 6.5 Mbps 54 Mbps 54 Mbps 162 Mbps 162 Mbps 270 Mbps 300 Mbps	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -85 dBm -72 dBm -72 dBm -87 dBm -82 dBm -78 dBm -78 dBm -74 dBm -74 dBm
(approximately) Receive sensitivity	+19 dBm +/- 1.0 dB maximum Mode 802.11b 802.11b 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g 802.11g EWC (2.4 GHz) EWC (2.4 GHz)	+17 dBm +/- 1.0 dB maximum Data rate 1 Mbps 11 Mbps 6 Mbps 6 Mbps 18 Mbps 48 Mbps 54 Mbps 6.5 Mbps 6.5 Mbps 81 Mbps 162 Mbps 270 Mbps 300 Mbps Minimum Throughput	+ 17 dBm +/- 1.0 dB maximum (total power in all transmit chains) Sensitivity -94 dBm -85 dBm -85 dBm -72 dBm -72 dBm -87 dBm -82 dBm -78 dBm -78 dBm -74 dBm -74 dBm



HP Compaq 8	8100	Elite	PC
-------------	------	-------	----

Technical Specifications - Communications	Technical Spec	ifications - (	Communications
---	----------------	----------------	----------------

	11 Mbps (802.11 b) 12 Mbps (802.11 g) 18 Mbps (802.11 g) 24 Mbps (802.11 g) 36 Mbps (802.11 g) 36 Mbps (802.11 g) 54 Mbps (802.11 g) 54 Mbps (802.11 g) 6.5 Mbps (20 MHz EWC) 13 Mbps (20 MHz EWC)	5.9 Mbps 6 Mbps 9 Mbps 12 Mbps 18 Mbps 21 Mbps 22.5 Mbps 4.5 Mbps 9 Mbps 13.5 Mbps
	EWC)	19 Mbra
	26 Mbps (20 MHz EWC) 39 Mbps (20 MHz EWC)	18 Mbps
	52 Mbps (20 MHz EWC)	27 Mbps 36 Mbps
	58.5 Mbps (20 MHz	40 Mbps
	EWC)	
	65 Mbps (20 MHz EWC)	45 Mbps
	78 Mbps (20 MHz EWC)	54 Mbps
	104 Mbps (20 MHz EWC)	·
	117 Mbps (20 MHz EWC)	•
	130 Mbps (20 MHz EWC)	
	13.5 Mbps (40 MHz EWC)	8 Mbps
	27 Mbps (40 MHz EWC)	16 Mbps
	40.5 Mbps (40 MHz EWC)	24 Mbps
	54 Mbps (40 MHz EWC)	32 Mbps
	81 Mbps (40 MHz EWC)	48 Mbps
	108 Mbps (40 MHz EWC)	64 Mbps
	121.5 Mbps (40 MHz EWC)	72 Mbps
	135 Mbps (40 MHz EWC)	81 Mbps
Security	<ul> <li>AES: CCM</li> <li>802.1x authenticatio</li> <li>WPA: 802.1x. WPA-</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> </ul>	
Antenna	HP part number 497792-0	001
Certifications	Wi-Fi certified	
Certifications for use by country	United States, Canada, Per	ru, Taiwan



## Technical Specifications - Communications

LSI PCIe x1 56K	Data Transmission	Technology speeds: 56,000 Kbps maximum downstream data, controllerless
International SoftModem		NOTE: 56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during download transmissions.
	Data Speeds	(Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/ 16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300
	Data Standards	ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell 212A, and Bell 103
	Fax Speeds	14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/s
	Fax Mode Capabilities	ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2
	Error Correction and Data Compression	V.44, 42bis, V.42 and MNP2-5
	Power Management	PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2, Appendix A. D0, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or beacon. Meets PCI Express 1.1 standard.
	Upgradeability	Driver upgradeable for future enhancements
	Video	ITU-T V.80 video ready interface
	Other	TIA/EIA 602 standard AT command set
		Integrated DTE interface with speeds of up to 115.2 Kbps, parallel 16550a UART-compatible interface
		Optional ring wakeup signal
	Operating Temperature	32° to 158° F (0° to 70° C)
	Operating Humidity	20% to 90%, non-condensing
	Power	Requires a 3.3-V auxiliary power rail on PCI express bus
		Uses only one PCI express load (i.e., one grant/request pair), one shared IRQ, one electrical load
	Chipset	LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and CardBus support
	Dimensions (L X H)	Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x 5.8 cm) and supports high- and low-profile brackets
	Connection	Single RJ-11 connector
	Other Features	Digital line protection, call progress monitoring via on-board piezo device, support for high profile and low profile brackets, PnP ID support
	Safety	UL recognized to UL 1950, 3rd edition (U.S. and Canada); IEC 950 (TUV, NEMKO, DEMKO, SEMKO); CE Mark, EC 950 (TUV, NEMKO, DEMKO, SEMKO, CE mark
	EMC	FCC Part 15, IC ES003, EN 55022, 3rd edition, EN 55024, annex A, EN 61000-4-6, EN 61000-4-8
	Telecom	FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals Not available in Korea or the Republic of South Africa.



### Technical Specifications - Communications

Other

The SV92EX device is packaged in a 32-pin micro leadless chip carrier (MLCC). The SV92EX is fully compliant with the PCI Express revision 1.1 specification. WHQL approved; ASPM compliant.



### HP Compaq 8100 Elite PC

# QuickSpecs

### Technical Specifications - Graphics

Intel® HD Graphics	3D/2D Controller VGA Controller DiaglauPoet	Microsoft DirectX® 10 based with support for Pixel Shader 3.0 Integrated
	DisplayPort Bus Type	Integrated, Multimode capable; supports HDCP PCI Express™ x16
	RAMDAC	Integrated, 350 MHz
	Memory	Graphics memory is shared with system memory. Graphics memory usage varies depending on the amount of system memory installed, BIOS settings, operating system, and system load. 32 MB is pre-allocated for graphics use at system boot time. Additional memory can be allocated at boot time by the BIOS for PAVP (Protected Audio Video Playback) support for playback of protected video content. For Vista, use of PAVP heavy mode preallocates an additional 96MB.
		Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
		Windows XP Memory Usage

#### Windows XP Memory Usage:

Total System Memory	Pre-Allocated (MB)	DVMT (MB)
.5GB	32	128
1.0GB	32	512
1.5GB	32	768
2GB & more	32	1024

#### Windows Vista Memory Usage:

(Assumes Management Engine , VT-d enabled and other memory allocated for other BIOS usage)

,	1					
		Avail	Total Avail	Dedicated	System	Shared
System	PVAP	System	GFX	Video	Video	System
Memory	F VAF	Memory	Memory	Memory	Memory	Memory
		(MB)	(MB)	(MB)	(MB)	(MB)
1 00	Lite	952	252	32	96	124
1 GB	Heavy	856	294	122	6	166
	Lite	1976	764	32	96	636
2 GB	Heavy	1880	806	122	6	678
	Lite	4024	1759	32	96	1631
4 GB	Heavy	3928	1759	122	6	1631
	Lite	6072	1759	32	96	1631
6 GB	Heavy	5976	1759	122	6	1631
	Lite	8120	1759	32	96	1631
8 GB	Heavy	8024	1759	122	6	1631

**Total Available GFX Memory**: Total graphics memory available to the system as reported by the OS.

**Dedicated Video Memory**: Memory owned and locked for graphics use as reported by the OS. (Preallocated)

System Video Memory: System memory locked and dedicated for graphics use.



### Technical Specifications - Graphics

	Shared System Memory: Memory dynamically allocated for Graphics use
HW Video Decode	Hardware Accelerated decode for MPEG2 encrypted video; support for PAVP Lite (default) and Heavy ( or Paranoid) modes
Maximum Color Depth	32 bits/pixel
Maximum Vertical Refresh Rate	85 Hz at up to 1920x1440, 75 Hz at 2048x1536. Varies with mode and configuration. See table below.
Multi-display Support	Integrated dual independent monitor support facilitated via one VGA port and one DisplayPort integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. DVI supported via optional HP DisplayPort to DVI-D adapter.
Graphics/Video API Support	Microsoft DirectX® 10, OpenGL® 1.5 (OpenGL® 2.0 available in a driver update)

#### **Resolutions Supported**

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60*

\* Only supported when using a DisplayPort connection

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.



Technical Specificatio	ons - Graphics	
NVIDIA Quadro NVS 290	Form Factor	Low Profile
256MB PCle Dual Head	Bus Type	PCle x16
	Memory	256 MB 400MHz DDR2 SDRAM unified frame buffer, Z-buffer and Texture storage
	Connector	DMS-59; includes one DMS-59 to Dual VGA cable. A DMS-59 to Dual DVI I cable is available as an option.
	Display resolution support	Dual integrated analog display controllers supporting up to two analog displays at 2048x1536 @ 85Hz on both displays or dual digital displays at 1920x1200 (single-link). NVIEW advanced multi-display desktop and application management seamlessly integrated into Microsoft Windows
	RAMDAC	Integrated dual 400MHz
	Color planes	32-bit color buffer
	Overlay planes	Hardware supported
	nView architecture	Advanced multi-display desktop & application management seamlessly integrated into Microsoft Windows.
	Multi-Monitor support	Dual monitor support
	DVI support	DMS-59 (to dual DVI-SL)
	High-definition Video Processor (HDVP)	Full-screen, full-frame video playback of HDTV and DVD content DVD-ready motion compensation for MPEG-2 Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0) IDCT motion compensation 5-tap horizontal by 3-tap vertical filtering 8:1 up/down scaling
	Supported graphics APIs	OGL 2.1 & DX10 Support; Shader Model 4.0
NVIDIA Quadro NVS 295	Form Factor	2.731 inches (H) $ imes$ 6.600 inches (L), Half-Height
Graphics Card	Graphics Controller	NVIDIA Quadro NVS 295 Graphics Board
	Bus Type	PCI Express x16, Generation 2.0
	Memory	256 MB GDDR3 SDRAM unified graphics memory
	Connectors	2 DisplayPort Comes with 2 DisplayPort to VGA Adapters NOTE: When purchased as an after-market option, this comes instead with 2 DisplayPort to DVI-D adapters.
	Maximum Resolution	Two DisplayPort outputs drive two digital displays up to 2560 x 1600
	Display Output	<ul> <li>Drives DisplayPort enabled digital displays at resolutions up to 2560 × 1600 at 60 Hz with reduced blanking</li> <li>Drives DVI enabled digital displays at resolutions up to 1920 × 1200 at 60 Hz with reduced blanking (through DisplayPort to DVI-D (single link) cable)</li> </ul>
	Supported Graphics APIs	OpenGL 3.0 DirectX 10.0



### Technical Specifications - Graphics

NVIDIA GeForce	Bus type	PCI Express (x16 lanes)
310 DP PCIe x16 Graphics Card	Maximum vertical refresh rate	85 Hz
	Display support	Integrated 400 MHz RAMDAC
	Display max resolution	2560x1600 digital, 2048 x 1536 analog

NVIDIA GeForce 310 DP PCle x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

Resolution	Maximum Refresh Rate (Hz)		
	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	60*	

\* Only supported when using a dual-link DVI or DP connection.

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

Board display options	Supports two displays via the DisplayPort and DVI connectors		
Board configuration	Specification	Description	
	Graphics Chip	RV620	
	Core clock	750 MHz	
	Memory clock	500 MHz	
	Frame buffer	512 MB DDR3, 64 bit wide	
<b>Audio Support</b> (through HDMI only)	Integrated HD Audio codec supports linear PCM and Dolby® Digital (7.1) audio formats for HDMI output		
Operating systems support	Windows 7 Home Basic <sup>*</sup> , Windows 7 Home Premium <sup>*</sup> , Windows 7 Professional Edition 32 <sup>*</sup> , Windows 7 Professional Edition 64 <sup>*</sup> , Windows 7 Ultimate Edition 32 <sup>*</sup> , Windows 7 Ultimate Edition 64 <sup>*</sup> , Windows Vista Business 32 <sup>†</sup> , Windows Vista Busine 64 <sup>†</sup> , Windows Vista Home Basic 32 <sup>†</sup> , Windows Vista Home Basic 64 <sup>†</sup> , Windows XP Professional or Windows XP Home 32 <sup>†</sup> .		
	*This system may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details.		
	Windows 7 Business disk may be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order at least 25 customer systems with the		



## Technical Specifications - Graphics

	same custom image
	† Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/systemrequirements.
	Linux x86 and x86_64 distributions using XFree86 or X.Org‡.
	‡Linux drivers are available from ATI's website and may be available in a Linux distribution. Refer to the Open Source and Linux from HP website: http://www.hp.com/wwsolutions/linux/products/clients/ for support information.
Core power	22 W (max)
Dimensions (H x D)	2.71 in x 6.60 in (68.90 mm x 167.65 mm)
Weight	0.30 lb (134.3 g)
Option kit contents	<ul> <li>NVIDIA GeForce 310 DP PCle x16 Graphics Cardwith full height bracket attached</li> <li>DVI to VGA adapter</li> <li>Software CD with graphics drivers</li> <li>Low profile bracket to convert the card for using in a low profile chassis</li> <li>Warranty documentation</li> </ul>
Compliance standards	EMC Emissions: a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office Use b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment c) Canadian Standard ICES-003 is equivalent to CISPR22 d) Taiwanese Standard BSMI e) Japanese VCCI f) Australian C-Tick g) Korean (MIC)
	EMC Immunity: CISPR 24:1997/EN 55024:1998 - Information Technology Equipment - Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4550 Dual Head PCle x16	Bus type Maximum vertical refresh rate	PCI Express (x16 lanes) 85 Hz
Graphics Card	Display support	Integrated 400 MHz RAMDAC
	Display max resolution	1900 x 1200 digital, 2048 x 1536 analog
	Board display options	Supports two displays via included DMS-59 to dual VGA cable or 2 DVI monitors via optional DMS-59 to dual DVI cable kit part number: DL139A. 4-pin mini-DIN S-video connector for TV output



### Technical Specifications - Graphics

Board configuration	<b>Specification</b> Graphics Chip Core clock Memory clock Frame buffer	Description RV710 600MHz 800 MHz 512 MB DDR3, 64 bit wide
Languages supported	Czechoslovakian, Danish, Dut Hebrew, Hungarian, Italian, Ja	:, Chinese Simplified, Chinese Traditional, ch, Finnish, French, German, Greek, apanese, Korean, Norwegian, Polish, Swedish, Thai, Turkish
Compliance standards	<ul> <li>Portuguese, Russian, Spanish, Swedish, Thai, Turkish</li> <li><u>EMC Emissions:</u> <ul> <li>a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home &amp; Office Use</li> <li>b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment</li> <li>c) Canadian Standard ICES-003 is equivalent to CISPR22</li> <li>d) Taiwanese Standard BSMI</li> <li>e) Japanese VCCI</li> <li>f) Australian C-Tick</li> <li>g) Korean (KCC)</li> </ul> </li> </ul>	

EMC Immunity:

CISPR 24:1997/EN 55024:1998 - Information Technology Equipment -Immunity Characteristics - Limits and Methods of Measurement.

#### ATI Radeon HD 4550 DH PCIe x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

Resolution	Maximum Refresh Rate (Hz)		
	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	N/A	
NOTE: 60-R denotes reduced blanking tim	ngs are used on single-link DVI connections	and may be used with other digital	
connections.			



### Technical Specifications - Graphics

ATI Radeon HD 4650 DP (1GB) PCle x16 Graphics Card	Bus type	PCI Express (x16 lanes)
	Maximum vertical refresh rate	85 Hz
	Display support	Integrated 400 MHz RAMDAC
	Display max resolution	2560 x 1600 digital, 2048 x 1536 analog

ATI Radeon HD 4650 DP (1GB) PCIe x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP

Resolution	Maximum Refresh Rate (Hz)		
	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	60*	

\* Only supported when using a dual-link DVI or DP connection

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections

Board display options	Supports two displays via included two DisplayPort and one Dual Link DVI-I connectors.		
Board configuration	Specification	Description	
	Graphics Chip	RV635	
	Core clock	725 MHz	
	Memory clock	500 MHz	
	Frame buffer	1 GB DDR3, 128 bit wide	
Languages supported	24 languages: English, Arabic, Chinese Simplified, Chinese Traditional, Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish, Portuguese, Russian, Spanish, Swedish, Thai, Turkish		
Operating systems support	Windows 7 Home Basic <sup>*</sup> , Windows 7 Home Premium <sup>*</sup> , Windows 7 Professional Edition 32 <sup>*</sup> , Windows 7 Professional Edition 64 <sup>*</sup> , Windows 7 Ultimate Edition 32 <sup>*</sup> , Windows 7 Ultimate Edition 64 <sup>*</sup> , Windows Vista Business 64 <sup>**</sup> , Windows Vista Business 32 <sup>**</sup> , Windows Vista Home Basic 32 <sup>**</sup> , Windows XP Professional or Windows XP Home 32 <sup>**</sup> .		
	DVD drive to install the Windows	a and/or separately purchased hardware and/or a 7 software and take full advantage of Windows 7 rosoft.com/windows/windows-7/ for details.	



## Technical Specifications - Graphics

		** Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/systemrequirements.	
		Linux x86 and x86_64 distributions using XFree86 or X.Org***.	
		*** Linux drivers are available from ATI's website and may be available in a Linux distribution. Refer to the Open Source and Linux from HP website: http://www.hp.com/wwsolutions/linux/products/clients/ for support information.	
Core power		56 W	
Option kit contents		<ul> <li>ATI Radeon HD 4650 DP (1GB) PCIe x16 Graphics Card with full height bracket attached</li> <li>DVI to VGA adapter</li> <li>DisplayPort to DVI-D adapter</li> <li>Software CD with graphics drivers</li> <li>Warranty documentation</li> </ul>	
		EMC Emissions: a) FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office Use b) CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information Technology Equipment c) Canadian Standard ICES-003 is equivalent to CISPR22 d) Taiwanese Standard BSMI e) Japanese VCCI f) Australian C-Tick g) Korean (MIC) <u>EMC Immunity:</u> CISPR 24:1997/EN 55024:1998 - Information Technology Equipment - Immunity	
		Characteristics - Limits and Methods of Measurement.	
HP ADD2 SDVO PCIe	Models	HP ADD2 SDVO DVI-D Out Adapter	
DVI-D Adapter	Form Factor	Low-profile card	
DVI-D Connector Dual Head Suppo		Digital connection only	
		rt Yes, when used with the integrated VGA connector	
I	Display Devices Supported	HP L1740 HP L1940T HP L2045W HP LP1965	
	NOTE: These graphics adapters offer optimal performance with any display that meets applicable VES/ standards.		
	Color Depth	All modes support 8-bpp, 16-bpp, and 24-bpp color depths	
	•	nnector Mechanically compliant with PCI-E standard Complies with the Intel ADD2 and Intel Serial Digital Video Output (SDVO) specifications	
	Dot Clock	165 MHz maximum	

#### Technical Specifications - Graphics

**Display Modes** 

Supports display modes that require up to 165-MHz bandwidth on the link, as shown in the following table

		45 5110 0011	In the following lable.		
Reso	lution	60-Hz LCD	60-Hz	75-Hz	85-Hz
Blar	nking	5% reduced	GTF	GTF	GTF
640 x 480	VGA	Yes	Yes	Yes	Yes
800 x 600	SVGA	Yes	Yes	Yes	Yes
1024 x 768	XGA	Yes	Yes	Yes	Yes
1280 x 1024	SXGA	Yes	Yes	No	No
1600 x 1200	UXGA	Yes	Yes	No	No

HP DisplayPort to DVI-D	Connectors	DisplayPort and DVI-D single link connector
Adapter	Adapter length	7.5 in (19.0 cm)
	Adapter weight	.10 lbs (.05 kg)

HP DisplayPort to VGA	Connectors	DisplayPort and VGA connector
Adapter	Adapter length	8 in (20 cm)
	Adapter weight	.1 lbs (.06 kg)
	Maximum vertical refresh rate	85 Hz
	Display support	162 MHz RAMDAC
	Display max resolution	1600x1200
	HP DisplayPort to VGA adapte	r display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP. Using the HP DisplayPort to VGA Adapter may require an update to the graphics driver installed on your system. To install the most up-todate graphics driver go to: www.hp.com.

Resolution	Max refresh rate
640x480	85
800x600	85
1024x768	85
1280x720	85
1280x1024	85
1440x900	75
1600x1200	60
1680x1050	60
1920x1080	60-R
1920x1200	60-R
NOTE: 60-R denotes reduced blanking timings are used. Not all	<u>.</u>

denotes reduced blanking timings are used. Not all monitors support reduc ed blanking fiming



3.5" 7200 RPM Serial

ATA Hard Drives

#### Technical Specifications - Hard Drives

500 GB	Capacity Height Width Interface Synchronous Transfer Rate (Maximum)	500,107,862,016 bytes 1 in (2.54 cm) Media diameter: 3.5 in (8.8 Physical size: 4 in (10.2 cm Serial ATA (3.0 Gb/s) Up to 3 Gb/s		
	Buffer	16 MB		
	Seek Time (typical reads,	Single Track	2.0 ms	
	includes controller overhead, including	Average	11 ms	
	settling)	Full-Stroke	21 ms	
	Rotational Speed	7,200 rpm		
	Logical Blocks	976,773,168		
	Operating Temperature	41° to 131° F (5° to 55° C)		
320 GB	Capacity	320,069,031,690 bytes		
	Height	1 in (2.54 cm)		
	Width	Media diameter: 3.5 in (8.89 cm)		
	_	Physical size: 4 in (10.2 cm)		
	Interface	Serial ATA (3.0 Gb/s)		
	Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s		
	Buffer	8 MB		
	Seek Time (typical reads,	Single Track	1.0 ms	
	includes controller overhead, including	Average	8.5 ms	
	settling)	Full-Stroke	18 ms	
	Rotational Speed	7,200 rpm		
	Logical Blocks	625,142,448		
	Operating Temperature	41° to 131° F (5° to 55° C)		
250 GB	Capacity	250,059,350,016 bytes		
	Height	1 in (2.54 cm)		
	Width	Media diameter: 3.5 in (8.89 cm)		
		Physical size: 4 in (10.2 cm)		
	Interface	Serial ATA (3.0 Gb/s)		
	Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s		
	Buffer	8 MB		



Technical Specifications - Hard Drives

,				
		Seek Time (typical reads,	Single Track	1.0 ms
		includes controller overhead, including	Average	8.5 ms
	settling)	•	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	488,397,168	
		Operating Temperature	41° to 131° F (5° to 55° C	C)
	160 GB	Capacity	160,041,885,696 bytes	
		Height 1 in (2.54 cm)		
	_	Width	Media diameter: 3.5 in (8	.89 cm)
			Physical size: 4 in (10.2 cr	n)
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	e Up to 3 Gb/s	
		Buffer	8 MB	
	includes controller overhead, including	Seek Time (typical reads,	Single Track	0.9 ms
			Average	9.3 ms
		overhead, including settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
	Logical Blocks	312,581,808		
		Operating Temperature	41° to 131° F (5° to 55° C	2)
10,000 RPM Serial ATA	160 GB	Capacity	160,041,885,696 bytes	
Hard Drives		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.0 in (7.62 cm)	
			Physical size: 4 in (10.2 cm	n)
		Interface	Serial ATA (1.5 Gb/s), Native Command Queuing enabled	
		<b>Synchronous Transfer</b> <b>Rate</b> (Maximum)	Up to 3.0 Gb/s	
		Cache	16 Mbytes	
		Seek Time (typical reads,	Single Track	0.3 ms
		includes controller	Average	4.6 ms
		overhead, including settling)	Full-Stroke	10.2 ms
		Rotational Speed	10,000 rpm	
		Logical Blocks	312,581,808	
		Operating Temperature	41° to 131° F (5° to 55° C	)
				1



#### Technical Specifications - Hard Drives

Solid State Drive	64 GB	Capacity	64 GB	
		NAND Flash Memory	Multi Level Cell (MLC) with	n wear leveling controller
		Interface type	SATA 3Gb/sec	
		<b>Dimensions-external</b> (W x H x D)	2.74 x 0.37 x 4 in (6.98 x	x 0.95 x 10.2 cm)
		Weight	0.14 lb (65 g)	
		Internal transfer rate	Write speed	Up to 220 MB/s
			Read speed	Up to 120 MB/s
		Host transfer rate	Ultra DMA mode	Up to 150 MB/s
		Power	DC power requirement	5 VDC 5%-100 mV ripple p-p
			Total power consumption	<1.12Watt
		Environmental	Temperature (operating)	$32^{\circ}$ to $158^{\circ}$ F (0° to $70^{\circ}$ C)
		(all conditions, non- condensing)	<b>Relative Humidity</b> (operating)	5% to 95%
			Maximum Wet Bulb Temperature (operating)	84° F (29° C)
		Regulations	UL, CSA, EN 60950-2000, CISPR Pub 22 Class B, CNS 13438, AS/NZS CISPR 22:2002 Class B, R1113 and C1172 Class B	
		NOTE: For solid state dis	k drives, GB means 1 billion	bytes. 16GB is the unformatted

**NOTE:** For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



USB

Dimensions (L × W × H)18.0 × 6.4 × 0.98 in (45.8 × 16.3 × 2.5 cmWeight2 lb (0.9 kg) minimumElectricalOperating voltage+ 5VDC ± 5%Power consumption50-mA maximum (with three LEDs ON)System interfaceUSB Type A plug connectorESDCE level 4, 15-kV air dischargeEMI - RFIConforms to FCC rules for a Class B comp deviceMicrosoft® PC 99 - 2001Functionally compliantMechanicalLanguagesMechanicalSwitch actuationSwitch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modifie tester)Switch typeContamination-resistant switch membrane Key-leveling mechanismsFor all double-wide and greater-length key Cable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanicall compliant AcousticsAcoustics43-dBA maximum sound pressure levelOperating humidity10% to 90% (non-condensing at ambient) Operating humidityOperating shock80 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak acceleration Non-operating vibrationNon-operating vibration2-g peak acceleration Drop (out of box)26 in (66 cm) on carpet, six-drop sequence Drop (in box)42 in (107 cm) on carrete, 16-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC	3 Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
Electrical       Weight       2 lb (0.9 kg) minimum         Electrical       Operating voltage       + 5VDC ± 5%         Power consumption       50-mA maximum (with three LEDs ON)         System interface       USB Type A plug connector         ESD       CE level 4, 15-kV air discharge         EMI - RFI       Conforms to FCC rules for a Class B comp device         Microsoft® PC 99 - 2001       Functionally compliant         Mechanical       Languages       38 available         Keycaps       Low-profile design       Switch actuation         Switch fife       20 million keystrokes (using Hasco modifie tester)         Switch type       Contamination-resistant switch membrane         Key-leveling mechanisms       For all double-wide and greater-length key Cable length       6 ft (1.8 m)         Microsoft PC 99 - 2001       Mechanically compliant         Acoustics       43-dBA maximum sound pressure level         Operating humidity       10% to 90% (non-condensing at ambient)         Non-operating       -22° to 140° F (-30° to 60° C)         temperature       Operating humidity       10% to 90% (non-condensing at ambient)         Non-operating humidity       10% to 90% (non-condensing at ambient)         Non-operating humidity       10% to 90% (non-condensing at ambient)         N			Dimensions $(L \times W \times H)$	
Electrical       Operating voltage       + 5VDC ± 5%         Power consumption       50-mA maximum (with three LEDs ON)         System interface       USB Type A plug connector         ESD       CE level 4, 15-KV air discharge         EMI - RFI       Conforms to FCC rules for a Class B comp device         Microsoft® PC 99 - 2001       Functionally compliant         Mechanical       Languages       38 available         Keycaps       Low-profile design         Switch actuation       55-g nominal peak force with tactile feedb         Switch type       Contamination-resistant switch membrane         Key-leveling mechanisms       For all double-wide and greater-length key         Cable length       6 ft (1.8 m)         Microsoft PC 99 - 2001       Mechanically compliant         Acoustics       43-dBA maximum sound pressure level         Operating temperature       50° to 120° ft (0° to 50° C)         Non-operating temperature       20° to 140° F (-30° to 60° C)         temperature       Operating shock       40 g, six surfaces         Non-operating shock       40 g, six surfaces         Non-operating shock       80 g, six surfaces         Non-operating vibration       2-g peak acceleration         Drop (out of box)       26 in (66 cm) on carpet, six-drop sequenc.<				
Power consumption50-mA maximum (with three LEDs ON)System interfaceUSB Type A plug connectorESDCE level 4, 15-kV air dischargeEMI - RFIConforms to FCC rules for a Class B comp deviceMicrosoft® PC 99 - 2001Functionally compliantMechanicalLanguagesSwitch actuation55-g nominal peak force with tactile feedbSwitch datuation55-g nominal peak force with tactile feedbSwitch typeContamination-resistant switch membraneKey-leveling mechanismsFor all double-wide and greater-length keyCable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelOperating temperature50° to 122° F (10° to 50° C)Non-operating humidity10% to 90% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating shock40 g, six surfacesOperating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration </th <th></th> <th>Electrical</th> <th>Operating voltage</th> <th><math>+ 5</math>VDC <math>\pm 5</math>%</th>		Electrical	Operating voltage	$+ 5$ VDC $\pm 5$ %
ESDCE level 4, 15-kV air dischargeEMI - RFIConforms to FCC rules for a Class B complexiceMicrosoft® PC 99 - 2001Functionally compliantMechanicalLanguagesMechanicalLanguagesSwitch actuation55-g nominal peak force with tactile feedbSwitch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modific tester)Switch typeContamination-resistant switch membrane Key-leveling mechanismsKey-leveling mechanismsFor all double-wide and greater-length key Cable lengthCable length6 ft (1.8 m) Microsoft PC 99 - 2001Moreosperating temperature50° to 122° F (10° to 50° C) Non-operating humidityNon-operating femperature50° to 122° F (10° to 50° C) temperatureOperating humidity10% to 90% (non-condensing at ambient) Non-operating shockNon-operating shock40 g, six surfaces Non-operating vibration A g peak acceleration Drop (out of box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC				50-mA maximum (with three LEDs ON)
EMI - RFIConforms to FCC rules for a Class B complexiceMicrosoft® PC 99 - 2001Functionally compliantMechanicalLanguagesKeycapsLow-profile designSwitch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modifile tester)Switch life20 million keystrokes (using Hasco modifile tester)Switch typeContamination-resistant switch membrane Key-leveling mechanismsFor all double-wide and greater-length key Cable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliant AcousticsAcoustics43-dBA maximum sound pressure level 50° to 122° F (10° to 50° C)Non-operating temperature50° to 122° F (10° to 50° C) temperatureNon-operating humidity10% to 90% (non-condensing at ambient) Non-operating shockNon-operating shock40 g, six surfaces A0 g, six surfacesOperating shock80 g, six surfaces (operating vibration Non-operating vibration 4-g peak acceleration Drop (out of box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			System interface	USB Type A plug connector
device         Microsoft® PC 99 - 2001       Functionally compliant         Mechanical       Languages       38 available         Keycaps       Low-profile design         Switch actuation       55-g nominal peak force with tactile feedb         Switch life       20 million keystrokes (using Hasco modifie tester)         Switch type       Contamination-resistant switch membrane         Key-leveling mechanisms       For all double-wide and greater-length key         Cable length       6 ff (1.8 m)         Microsoft PC 99 - 2001       Mechanically compliant         Acoustics       43-dBA maximum sound pressure level         Operating temperature       50° to 122° F (10° to 50° C)         Non-operating temperature       50° to 120° F (-30° to 60° C)         Temperature       10% to 90% (non-condensing at ambient)         Non-operating humidity       10% to 80% (non-condensing at ambient)         Non-operating shock       40 g, six surfaces         Operating vibration       2-g peak acceleration         Non-operating vibration <th></th> <th></th> <th>ESD</th> <th>CE level 4, 15-kV air discharge</th>			ESD	CE level 4, 15-kV air discharge
MechanicalLanguages38 availableKeycapsLow-profile designSwitch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modifie tester)Switch typeContamination-resistant switch membrane Key-leveling mechanismsKey-leveling mechanismsFor all double-wide and greater-length key Cable lengthAcoustics43-dBA maximum sound pressure levelDeparating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)Non-operating humidity10% to 90% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			EMI - RFI	Conforms to FCC rules for a Class B computing device
Key capsLow-profile designSwitch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modifie tester)Switch typeContamination-resistant switch membraneKey-leveling mechanismsFor all double-wide and greater-length key Cable lengthCable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliant AcousticsAcoustics43-dBA maximum sound pressure levelOperating temperature50° to 122° F (10° to 50° C) Non-operating temperatureOperating humidity10% to 90% (non-condensing at ambient) Non-operating humidityNon-operating shock40 g, six surfaces Non-operating shockNon-operating vibration2-g peak acceleration Non-operating vibrationNon-operating vibration2-g peak acceleration LoperotionNon-operating vibration2-g peak acceleration LoperotionNon-operating vibration4-g peak accelerationNon-operating vibration4-g peak acceleration LoperotionNon-operating vibration4-g peak acceleration LoperotionNon-operating vibration4-g peak acceleration LoperotionNon-operating vibration4-g peak acceleration LoperotionNon-operating vibration4-g peak acceleration Loperotion<			Microsoft® PC 99 - 2001	Functionally compliant
Switch actuation55-g nominal peak force with tactile feedbSwitch life20 million keystrokes (using Hasco modifie tester)Switch typeContamination-resistant switch membrane (Cable lengthKey-leveling mechanismsFor all double-wide and greater-length key Cable lengthAcoustics43-dBA maximum sound pressure levelDeperating temperature50° to 122° F (10° to 50° C) Non-operating temperatureNon-operating humidity10% to 90% (non-condensing at ambient) Non-operating shockNon-operating shock40 g, six surfaces 40 g, six surfacesNon-operating vibration2-g peak acceleration 4-g peak acceleration Drop (out of box)Drop (in box)42 in (107 cm) on concrete, 16-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC		Mechanical	Languages	38 available
Switch life20 million keystrokes (using Hasco modifie tester)Switch typeContamination-resistant switch membrane Key-leveling mechanismsKey-leveling mechanismsFor all double-wide and greater-length key Cable lengthCable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelOperating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)temperatureOperating humidityNon-operating shock40 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Keycaps	Low-profile design
InstructionSwitch typeContamination-resistant switch membraneKey-leveling mechanismsFor all double-wide and greater-length keyCable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelDerating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)temperatureOperating humidityNon-operating humidity10% to 90% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration4-g peak accelerationDrop (in box)26 in (66 cm) on carpet, six-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceDrop XUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Switch actuation	55-g nominal peak force with tactile feedback
Key-leveling mechanismsFor all double-wide and greater-length key Cable lengthCable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelEnvironmentalOperating temperature50° to 122° F (10° to 50° C)Non-operating temperatureOperating humidity10% to 90% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequenc Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Switch life	20 million keystrokes (using Hasco modified tester)
Cable length6 ft (1.8 m)Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelOperating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)Operating humidity10% to 90% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration4-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Switch type	Contamination-resistant switch membrane
Microsoft PC 99 - 2001Mechanically compliantAcoustics43-dBA maximum sound pressure levelEnvironmentalOperating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)Operating humidity10% to 90% (non-condensing at ambient)Non-operating humidity0% to 80% (non-condensing at ambient)Operating shock40 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequence Drop (in box)ApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Key-leveling mechanisms	For all double-wide and greater-length keys
Acoustics43-dBA maximum sound pressure levelEnvironmentalOperating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)Operating humidity10% to 90% (non-condensing at ambient)Non-operating humidity20% to 80% (non-condensing at ambient)Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration4-g peak accelerationNon-operating vibration26 in (66 cm) on carpet, six-drop sequenceDrop (out of box)26 in (66 cm) on concrete, 16-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Cable length	6 ft (1.8 m)
EnvironmentalOperating temperature50° to 122° F (10° to 50° C)Non-operating temperature-22° to 140° F (-30° to 60° C)Operating humidity10% to 90% (non-condensing at ambient)Non-operating humidity10% to 90% (non-condensing at ambient)Non-operating humidity20% to 80% (non-condensing at ambient)Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration26 in (66 cm) on carpet, six-drop sequenceDrop (in box)26 in (107 cm) on concrete, 16-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, MIC			Microsoft PC 99 - 2001	Mechanically compliant
Non-operating temperature-22° to 140° F (-30° to 60° C)Operating humidity10% to 90% (non-condensing at ambient)Non-operating humidity20% to 80% (non-condensing at ambient)Non-operating shock40 g, six surfacesNon-operating shock80 g, six surfacesNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationNon-operating vibration2-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Acoustics	43-dBA maximum sound pressure level
temperatureOperating humidity10% to 90% (non-condensing at ambient)Non-operating humidity20% to 80% (non-condensing at ambient)Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesOperating vibration2-g peak accelerationNon-operating vibration4-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC		Environmental	Operating temperature	50° to 122° F (10° to 50° C)
Non-operating humidity20% to 80% (non-condensing at ambient)Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesOperating vibration2-g peak accelerationNon-operating vibration4-g peak accelerationNon-operating vibration26 in (66 cm) on carpet, six-drop sequenceDrop (in box)26 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC				-22° to 140° F (-30° to 60° C)
Operating shock       40 g, six surfaces         Non-operating shock       80 g, six surfaces         Operating vibration       2-g peak acceleration         Non-operating vibration       4-g peak acceleration         Drop (out of box)       26 in (66 cm) on carpet, six-drop sequence         Drop (in box)       42 in (107 cm) on concrete, 16-drop sequence         UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Operating humidity	10% to 90% (non-condensing at ambient)
Non-operating shock       80 g, six surfaces         Operating vibration       2-g peak acceleration         Non-operating vibration       4-g peak acceleration         Drop (out of box)       26 in (66 cm) on carpet, six-drop sequence         Drop (in box)       42 in (107 cm) on concrete, 16-drop sequence         Approvals       UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Non-operating humidity	20% to 80% (non-condensing at ambient)
Operating vibration       2-g peak acceleration         Non-operating vibration       4-g peak acceleration         Drop (out of box)       26 in (66 cm) on carpet, six-drop sequence         Drop (in box)       42 in (107 cm) on concrete, 16-drop sequence         Approvals       UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Operating shock	40 g, six surfaces
Non-operating vibration4-g peak accelerationDrop (out of box)26 in (66 cm) on carpet, six-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Non-operating shock	80 g, six surfaces
Drop (out of box)26 in (66 cm) on carpet, six-drop sequenceDrop (in box)42 in (107 cm) on concrete, 16-drop sequenceApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Operating vibration	2-g peak acceleration
Drop (in box)42 in (107 cm) on concrete, 16-drop sequApprovalsUL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Non-operating vibration	4-g peak acceleration
Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC			Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
••			<b>Drop</b> (in box)	42 in (107 cm) on concrete, 16-drop sequence
Eraonomic compliance ANSI HFS 100. ISO 9241-4. and TUVGS		Approvals	UL, CSA, FCC, CE Mark,	TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
		Ergonomic compliance	ANSI HFS 100, ISO 9241	-4, and TUVGS
Kit contents Keyboard, installation guide, warranty card, safety and comfort guide		Kit contents	Keyboard, installation guid	le, warranty card, safety and comfort guide



invent

HP Compaq	8100	Elite	PC
-----------	------	-------	----

Technical Specifications - Input/Output Devices	Technical	<b>Specifications</b>	: - Input/Ou	tput Devices
---	-----------	-----------------------	--------------	--------------

PS/2 Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Dimensions (L $\times W \times H$ )	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	$+$ 5VDC $\pm$ 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	PS/2 6-pin mini din connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidity	20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		<b>Drop</b> (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark,	TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
	Ergonomic compliance	ANSI HFS 100, ISO 9241	-4, and TUVGS
HP USB Smartcard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Form factor	USB basic Smart Card keyboard
		Colors	Carbonite/Silver
		<b>Dimensions</b> (H $\times$ W $\times$ D)	18.2 x 6.3 x 1.3 in (46.3 x 16.1 x 3.3 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	$+$ 5VDC $\pm$ 5%
	DA - 13524 V	Vorldwide — Version 5 — F	ebruary 3, 2010 Page 4

1 / 1	<b>D</b>	
	Power consumption	100-mA maximum (with four LEDs ON)
	System interface	USB Type A plug connector
	ESD	CE level 4, 15-kV air discharge
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft PC 99 - 2001	Functionally compliant
Mechanical	Languages	30+ available
	Keycaps	Low-profile design
	Switch actuation	55 g nominal peak force with tactile feedback
	Switch life	20 million keystrokes (using Hasco modified tester)
	Switch type	Contamination-resistant membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	<b>Drop</b> (in box)	42 in (107 cm) on concrete, 16-drop sequence
SMARTCARD function	Support	All ISO 7816 smart cards
	Interface	Reads from and writes to all ISO7816-1, 2, 3, 4 memory and microprocessor smart cards (T=0, T=1)
	Chipset	SCM STCII
	Standard APIs supported	PC/SC, EMV2000, SET
	Power	USB Port
		Short circuit detection (protects smart card and reader)
	Power consumption	reader) Power supply compliant with ISO7816 and EMV (5V, 60 mA) Supports 3-V and 5-V cards 250-mA maximum draw (50 mA for the keyboard with three LEDs ON and 200-mA maximum startup current using a high-current, 60-mA smart card)



reenned opeemeen		evices		
		Communication	From card	Programmable from 9,600 baud to 115,200 baud
			From computer	Up to 38,400 baud
		Landing mechanism	Contact device	Friction contact
		-	Card insertions rating	Up to 100,000 insertion cycles
		Interface modes	USB communications the SCM protocol	nrough USB port
			Automatic card insertio	n/removal detection
		Reader performance interface	USB connection	
		Electro-magnetic	Europe	89/336/CEE guideline
		standards	USA	USAFCC part 15
HP PS/2 Optical Scroll	Dimensions (H x L x W)	3.95 x 6.21 x 11.7 cm (1	.56 x 2.44 x 4.61 in)	
Mouse	Weight	4.44 oz (126 g)		
	Environmental	Operating temperature	-32° to 104°F (0° to 40° C)	
		Non-operating temperature	-4° to 140°F ( -20° to 6	0° C)
		Operating humidity	10% to 90% (non cond	ensing at ambient)
		Non-operating humidity	10% to 90% non conde	ensing
		Operating shock	40 g, 6 surfaces	
		Non-operating shock	80 g, 6 surfaces	
		Operating vibration	2 g peak acceleration	
		Non-operating vibration	4 g peak acceleration	
		<b>Drop</b> (out of box)	80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 direction except the cal face	
	Electrical	Operating voltage	5 VDC ± 10%	
		Power consumption	100mA	
		System consumption	PS/2 mini-din connector	
		ESD	CE level 4, 15 kV air discharge	
		EMI-RFI	Conforms to FCC rules device	for a Class B computing
		Microsoft PC99 - 2001	Functionally compliant	
	Mechanical	Resolution	$400 \pm 20\%$ DPI	
		Tracking speed	10 in/s (25.4 cm/s) ma	ximum
		Acceleration	100 in/s/s (2.54 m/s/s	)
		Switch actuation	61 g nominal peak forc	ce
		Switch life	3,000,000 operations tester)	(using Hasco modified
		Switch type	Low force micro-switche	es



1 , 1		
	Tracking mechanism life	155 mi (250 km) at average speed of 10 in/s
	-	6 ft (1.8 m)
	Microsoft PC99 - 2001	Mechanically compliant
Scroll wheel	Width	8 mm
	Diameter	1.01 in (25.6 mm)
	Maximum rotation speed	48 rats/sec
	Switch type	Light force micro-switch
	Switch life	1 million operations
	Mechanical life	Minimum 200,000 revolutions
Regulatory approvals	Compliant	UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI BSMI, C-Tick, MIC
Dimensions (H x L x W)	1.5 x 4.5 x 2.5 in (3.8 x 11	l.6 x 6.3 cm)
Weight	0.27 lb (0.12 kg)	
Cable length	72.8 in (185 cm)	
System requirements	Microsoft Windows 95, 98, Available USB port	, 2000, Me, XP and Vista
Scroll Wheel	24	
Maximum Rotation Speed	48 rats/sec	
Switch Type	wheel	
Switch Life	Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times	
Environmental	Operating Temperature	32° to 104° F (0° to 40° C)
	Non-operating Temperature	-4° to 140° F (-20° to 60° C)
	Operating Humidity	10% to 90% (non-condensing at ambient)
	Non-operating Humidity	20% to 80% (non-condensing at ambient)
	Operating Shock	40 g, six surfaces
	Non-operating Shock	80 g, six surfaces
	Operating Vibration	2-g peak acceleration
	Non-operating Vibration	4-g peak acceleration
Electrical	Operating Voltage	$+$ 5VDC $\pm$ 5%
	Power Consumption	
	MTBF	> 150,000 hrs
	ESD	IEC-61000-4-2 criteria B, Contact discharge: +/- 4kV, Air discharge: +/- 8kV
	EMI-RFI	FCC Class B
	<b>D</b> CO0	
	PC98	PC 99 Compliant
Mechanical	PC98 Resolution	800dpi
	Regulatory approvals Dimensions (H x L x W) Weight Cable length System requirements Scroll Wheel Maximum Rotation Speed Switch Type Switch Life Environmental	Cable length Microsoft PC99 - 2001Scroll wheelWidth Diameter Maximum rotation speed Switch type Switch life Mechanical lifeRegulatory approvalsCompliantDimensions (H × L × W)1.5 × 4.5 × 2.5 in (3.8 × 11 0.27 lb (0.12 kg) Cable lengthSystem requirements72.8 in (185 cm) Microsoft Windows 95, 98 Available USB portScroll Wheel24 48 rats/secScroll Wheel24 Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times 

	Acceleration	0.5mm
	Switch Actuation	0.6N (60gf)
	Switch Life	Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times
	Cable Length	1850mm
	PC98-99	PC99 compliant
Regulatory Approvals	UL60950-1, UL 94, UL 74 TUV/GS: EN 60950-1, EN FCC Class B, UL 1950, cl	· · · · ·



#### Technical Specifications - Optical Storage

HP Blu-ray Writer Drive	Height Orientation Interface type Disc capacity Dimensions (W x H x D) Weight (max)	5.25-inch, half-height, tra Either horizontal or vertica SATA/ATAPI 50 GB DL or 25 GB stand 5.9 x 1.7 x 7.5 in (15.0 x 2.0 lb (907g)	lard 4.4 x 19.0 cm)	
			Single-layer	Double-layer
	Write speed	BD-R	2x, 4x CLV, 6x CAV	2x, 4x CLV
		BD-RE	2.3x	2x CLV
		DVD-R	2x, 4x CLV, 8x ZCLV, 8x, 12x PCAV, 16x CA	
		DVD-RW	1x, 2x, 4x, 6x CLV	Not supported
		DVD+R	2.4x, 4x CLV, 8x ZCLV, 8x, 12x PCAV, 16x CAV	
		DVD+RW	2.4x, 4x, 6x CLV, 8x ZCLV	Not supported
		DVD-RAM	2x, 3x CLV, 3-5x PCAV	
		CD-R	8x,16x CLV, 24x, 32x F	PCAV, 40x CAV
		CD-RW	4x, 10x, 16x CLV, 24x	ZCLV
			Single-layer	Double-layer
	Read speeds	BD-ROM	6x CAV	4.8x CAV
		BD-R	6x CAV	4.8x CAV
		BD-RE (SL/DL)	4.8x CAV	4.8x CAV
		DVD-ROM	16x CAV	8x CAV
		DVD-R	12x CAV	8x CAV
		DVD-RW	10x CAV	Not support
		DVD+R	12x CAV	8x CAV
		DVD+RW	10x CAV	Not support
		<b>BDMV</b> (AACS Compliant Disc)	4.8x CAV	
		DVD-RAM	2x, 3x CLV, 3x-5x PCA	/
		<b>DVD-Video</b> (CSS Compliant Disc)	8x CAV	
		CD-R/RW/ROM	40x / 40x / 40x CAV	
		CD-DA (DAE)	32x CAV	
		80 mm CD	16x CAV	
	Sustained Transfer rate	BD-ROM	26.97 MB/s (6x) max	
		DVD-ROM	16.62 MB/s (16x) max.	
		CD-ROM	6,000 KB/s (40x) max.	
	Burst Transfer rate		1.5Gbps bits/s (10b sic 1.2Gbps bits/s (8b side	



#### Technical Specifications - Optical Storage

	Multimedia MPC-3 compliant		Yes	
	Access times (typical reads, including	Random	DVD: < 140 ms (typical), CD: < 125 ms (typical)	
	setting)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)	
	Power	Source	SATA DC power receptacle	
		DC Power Requirement	5 VDC $\pm$ 5%-100 mV ripple p-p 12 VDC $\pm$ 5%-200 mV ripple p-p	
		DC Current	5 VDC -1000 mA typical, 1600 mA maximum 12 VDC -600 mA typical, 1400 mA maximum	
	Environmental	Temperature (operating)	41° to 122° F (5° to 50° C)	
	(all conditions non-condensing)	<b>Relative Humidity</b> (operating)	10% to 90%	
		Maximum Wet Bulb Temperature (operating)	86° F (30° C)	
HP SuperMulti LightScribe	Height	5.25-inch, half-height, tra	y-load	
DVD Writer Drive	Orientation	Either horizontal or vertical		
	Interface type	SATA/ATAPI		
	Disc capacity	8.5 GB DL or 4.7 GB standard		
	<b>Dimensions</b> ( $W \times H \times D$ )	5.9 x 1.7 x 8.0 in (15.0 x	4.4 x 20.3 cm)	
	Weight (max)	2.6 lb (1.2 kg)		
	Write speeds	DVD-RAM	Up to 12X	
		DVD+R	Up to 16X	
		DVD+RW	Up to 8X	
		DVD+R DL	Up to 8X	
		DVD-R DL	Up to 8X	
		DVD-R	Up to 16X	
		DVD-RW	Up to 6X	
		CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Read speeds	DVD-RAM	Up to 12X	
		DVD+RW, DVD-RW, DVD+R DL, DVD-R DL	Up to 8X	
		DVD-ROM DL	Up to 8X	
		DVD-ROM, DVD+R, DVD-R	Up to 16X	
		CD-ROM, CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Access time (typical reads, including	Random	DVD: < 140 ms (typical), CD: < 125 ms (typical)	
	settling)	Full Stroke	DVD: $<$ 250 ms (seek), CD: $<$ 210 ms (seek)	
	Power	Source	SATA DC power receptacle	



Technical Specifica	tions - Optical Storage			
		DC Power Requirement	5 VDC ± 5%-10	00 mV ripple p-p
			12 VDC ± 5%-2	200 mV ripple p-p
		DC Current	5 VDC (< 1000 maximum)	mA typical, 1600 mA
				mA typical, 1400 mA
			maximum)	
	Environmental conditions	Temperature	41° to 122° F (5	o° to 50° C)
	(operating - non-	Relative Humidity	10% to 90%	
	condensing)	Maximum Wet Bulb Temperature	86° F (30° C)	
HP DVD-ROM Drive	Height	5.25-inch, half-height, tr	ay-load	
	Orientation	Either horizontal or vertical		
	Interface type	SATA/ATAPI		
	Disc capacity	Single layer: Up to 4.7 GB (6 times capacity of CD-ROM) Double layer: Up to 8.5 GB (12 times capacity of CD-ROM)		
	<b>Dimensions</b> ( $W \times H \times D$ )	5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)		
	Weight (max)	2.6 lb (1.2 kg)		
	Read speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL	Up to 8X	
		DVD-ROM	Up to 16X	
		DVD-RAM	Up to 4X	
		CD-ROM, CD-R	Up to 48X	
		CD-RW	Up to 32X	
	Removable Storage -	Media	Read	Write
	Media Compatibility - DVD-ROM	CD-ROM	Yes	No
		CD-R	Yes	No
		CD-RW	Yes	No
		DVD-ROM	Yes	No
		DVD-ROM DL	Yes	No
		DVD-RAM	Yes	No
		DVD+R	Yes	No
		DVD+R DL	Yes	No
		DVD+RW	Yes	No
		DVD-R	Yes	No
		DVD-RW	Yes	No
		DVD-R DL	Yes	No
	Access times (typical reads, including	Random	(typical)	s (typical), CD: < 125 ms
	setting)	Full Stroke		s (seek), CD: < 210 ms (seek)
		Cache Buffer	2 MB (minimum)	)



#### Technical Specifications - Optical Storage

	Data Transfer Modes	ATA PIO mode 4 (16.7 MB/s); ATA Multi-word DMA mode 2 (16.7 MB/s); ATA UltraDMA Mode 3 (44.4 MB/s -default)
Power	Source	SATA DC power receptacle
	DC Power Requirement	5 VDC $\pm$ 5%-100 mV ripple p-p 12 VDC $\pm$ 5%-200 mV ripple p-p
	DC Current	5 VDC - <1000 mA typical, < 1600 mA maximum 12 VDC -< 600 mA typical, < 1400 mA maximum
Environmental	Temperature	41° to 122° F (5° to 50° C)
(all conditions	Relative Humidity	10% to 90%
non-condensing)	Maximum Wet Bulb Temperature	86° F (30° C)



#### Technical Specifications - Removable Storage

HP 22-in-1 Media Card Reader (with 1394)	USB Interface	USB 2.0 High-speed interface	
		NOTE: Requires the 2.0 port or a USB 2.	USB cable to be connected to the internal USB .0 PCI card.
	1394 Interface	Two IEEE-1394a external p pass through cable on the	ports; 1 IEEE-1394a internal port (connects to the media card reader)
	Advance protocol support	<ul> <li>Supports hardware (</li> <li>Supports MS 4-bit p</li> <li>Supports MS-PRO 4</li> <li>Supports MS PRO-H</li> <li>Supports SD 4-bit po</li> <li>Supports high-speed</li> <li>Supports high-speed</li> </ul>	-bit parallel transfer mode G Duo 4-bit parallel transfer mode
	Supported media type		II MC) MediaCard (RS MMC) 2 (MMC Plus, including MMC Plus HC) MediaCard 4.2 (MMC Mobile, including MMC (SD) Capacity (SDHC) ity MS Duo) MS PRO) Duo (MS PRO Duo) HG Duo Stick (MG)
	Supported media type with card adapter	<ul><li>Memory Stick Micro</li><li>MMC Micro</li></ul>	(M2)
	Environmental	Operational Environmental Extremes	Test Parameters/Conditions - Power applied, unit operating on system ±5% nominal supply voltage. 10°C 10% R.H. = 24 hours 10°C 90% R.H. = 24 hours 20°C 90% R.H. = 24 hours



 $30^{\circ}C$  90% R.H. = 24 hours 40°C 90% R.H. = 24 hours 50°C 90% R.H. = 24 hours

Technical Specifications -	Removable Storage
----------------------------	-------------------

Approvals

	50°C 10% R.H. = 24 hours
Storage Environmental Extremes	Test Parameters/Conditions 140°F (60°C) @ 80% R.H. for 96 hours -22°F (-30°C) @ 20% R.H. for 48 hours No power applied Delta °C < 1.0°C/min Delta % R.H. < 1.5% R.H./min
	ant with USB Mass Storage Class Bulk only Transport ompliant Intel Front Panel I/O Connectivity Design

FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUV-T



#### Technical Specifications - Environmental Data

**Eco-Label Certifications &** This product has received or is in the process of being certified to the following approvals and may be declarations labeled with one or more of these marks:

- US ENERGY STAR ®
- IT ECO declaration
- EPEAT Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.

#### Convertible Minitower

Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	46.9450 W	47.0125 W	46.5123 W
Sleep (Energy Star low power mode)	3.7745 W	3.7250 W	3.6882 W
Off	0.7562 W	0.8895 W	0.7751 W
Heat Dissipation (typically configured)*	115 VAC	230 VAC	100 VAC
Normal Operation	161 BTU/hr	161 BTU/hr	159 BTU/hr
Sleep	13 BTU/hr	13 BTU/hr	13 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

\* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Additional Performance	HP Compaq 8100 Elite CMT		
Data (for configuration	Processor	Intel i5-660	
specified in table)	Memory size	2 x 1 GB	
	Memory Type	DDR3 1333	
	Graphics Memory	32 + 32 + 667 MB	
	Graphics adapter/card	i5 series integrated	
	Graphics driver revision	1968	
	Resolution and color depth	1280 x 1024 x 32B	
	Video Refresh	75 Hz	
	HD	160GB – 7200 rpm	
	Partition type	NTFS	
	ODD	Lightscribe DVD/RW	
	OS rev, build and spack	Windows 7 Pro 32	
	Power Supply	High Efficiency	
	SYSMark 2007 Rating	185	
	E Learning	165	
	3D	196	
	Video Creation	178	
	Productivity	202	
	Windows Experience Index - Base	4.8	



HP Compaq	8100	Elite	PC
-----------	------	-------	----

Technical Specifications - Environmental Data

	_	
	Processor	6.9
	Memory	5.5
	Graphics	4.8
	Gaming Graphics	5.2
	HDD	5.9
	PCMark05 - Version 120 / 121	
	Overall	7594
	CPU	9398
	Memory	7756
	Graphics	3243
	HDD	6259
	Power readings - Watts	
	PCM05 Peak Watts	72.18
	PCM05 Average Watts	49.02
	PCM05 Watt-hours	18.4
Declared Noise Emissior (in accordance with ISO 7779 and ISO 9290		
System Fan Off	Sound Power	Sound Pressure
	(LWAd, bels)	(LpAm, decibels)
Idle	3.8	21
Fixed Disk (random writes)	3.8	21
Batteries	This battery(s) in this product comply with	EU Directive 2006/66/EC
	Batteries used in the product do not cont	ain:
	<ul><li>Mercury greater the 5ppm by weig</li><li>Cadmium greater than 10ppm by</li></ul>	
	Battery size: CR2032 (coin cell) Battery type: Li-Ion	
Additional Information	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.</li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.</li> <li>This product is 90% recyclable when properly disposed of at end of life.</li> </ul>	



	Tec	:hnical	<b>Specifications</b>	- Environm	ental Data
--	-----	---------	-----------------------	------------	------------

#### Packaging Materials

- External:
  - O Corrugated 2550 g
- Internal:
  - O Polyethylene high density 160 g
- The corrugated packaging material is made from 37% recycled content.
- The Polyethylene high density packaging material is made from 100% recycled content.

Small Form Factor			
Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	39.787 W	39.547 W	39.865 W
Sleep (Energy Star low power mode)	3.2283 W	3.4659 W	3.2186 W
Off	1.0477 W	1.2128 W	1.0345 W
Heat Dissipation (typically configured)*	115 VAC	230 VAC	100 VAC
Normal Operation	161 BTU/hr	161 BTU/hr	136 BTU/hr
Sleep	13 BTU/hr	13 BTU/hr	11 BTU/hr
Off	3 BTU/hr	3 BTU/hr	4 BTU/hr

\* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Additional Performance	HP Compaq	8100 Elite SFF
Data (for configuration	BIOS version	786H1 – 0.51
specified in table)	Processor	Intel i5-660 - Turbo enabled
	Memory size	2 x 1 GB
	Memory Type	DDR3 1333
	Graphics Memory	32 + 32 + 667 MB
	Graphics adapter/card	i5 series integrated
	Graphics driver revision	1968
	Resolution and color depth	1280 x 1024 x 32B
	Video Refresh	75 Hz
	HD	160GB – Seagate 7200 rpm
	Partition type	NTFS
	ODD	Lightscribe DVD/RW
	OS rev, build and spack	Windows 7 Pro 32
	run by	CPA Lab
	PS Vendor	Lite-On HiPro
	PS Model	503375-001 503376-001



Technical Specifications - Environmental Data

			55.4
	EPA / non-EPA	non-EPA	EPA
	Power readings – Watts	0.40	0.40
	Off – WOL with F10 Setup S5 Max Savings	0.48	0.42
	Off –WOL	0.72	0.67
	Off + WOL	0.72	0.67
	Sleep / Standby	2.48	2.48
	Idle	39.77	30.44
	PCM05 Peak Watts	89.51	74.32
	PCM05 Average Watts	61.65	49.52
	PCM05 Watt-hours	23.43	18.75
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)			
System Fan Off	Sound Power	Sound F	Pressure
	(LWAd, bels)	(LpAm, d	
Idle	3.7	2	7
Fixed Disk (random writes)	3.7 27		7
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC		
	Batteries used in the product do not cor	itain:	
	<ul><li>Mercury greater the 5ppm by wei</li><li>Cadmium greater than 10ppm b</li></ul>	•	
	Battery size: BR-2032 Battery type: Lithium		
Additional Information	<ul> <li>Battery type: Lithium</li> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.</li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.</li> <li>This product contains 0% post consumer recycled plastic (by wt.)</li> <li>This product is 95.1% recyclable when properly disposed of at end of life.</li> </ul>		
	Packaging Materials		
	• External:		



Technical	<b>Specifications</b>	- Environment	al Data
-----------	-----------------------	---------------	---------

- O Corrugated 1700 g
- Internal:
  - O EPE Expanded Polyethylene 160 g
  - O Polyethylene low density foam 160 g
- The Corrugated Carton packaging material is made from 100% recycled content.
- The EPE Expanded Polyethylene packaging material is made from 100% recycled content
- The Polyethylene low density foam packaging material is made from 100% recycled content

#### Convertible Minitower and Small Form Factor

RoHS Compliance	Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at: http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
Packaging	<ul> <li>Asbestos</li> <li>Certain Azo Colorants</li> <li>Certain Brominated Flame Retardants – may not be used as flame retardants in plastics</li> <li>Cadmium</li> <li>Chlorinated Hydrocarbons</li> <li>Chlorinated Paraffins</li> <li>Formaldehyde</li> <li>Halogenated Diphenyl Methanes</li> <li>Lead carbonates and sulfates</li> <li>Lead and Lead compounds</li> <li>Mercuric Oxide Batteries</li> <li>Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.</li> <li>Ozone Depleting Substances</li> <li>Polybrominated Biphenyl Ethers (PBBs)</li> <li>Polybrominated Biphenyl Oxides (PBBOs)</li> <li>Polybrominated Biphenyl (PCB)</li> <li>Polychlorinated Terphenyls (PCT)</li> <li>Polychlorinated Terphenyls (PCT)</li> <li>Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.</li> <li>Radioactive Substances</li> <li>Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)</li> </ul>
Packaging	HP follows these guidelines to decrease the environmental impact of product



Technical Specifications - Environmental Data	Technical S	Specifications	- Environm	iental Data
---	-------------	----------------	------------	-------------

packaging:

<ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> <li>Design packaging materials for ease of disassembly.</li> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/operations/ envmanagement.html

Copyright © 2010 Hewlett-Packard Development Company, L.P.

All rights reserved. Microsoft, Windows, Windows 7, and Windows Vista are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Core, and Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a registered trademark of Bluetooth SIG, Inc., in the U.S. and other countries. All other product names mentioned herein may be trademarks of their respective companies.

The information contained herein is subject to change without notice and is provided "as is" without warranty of any kind. The warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

